

TLE5012

TLE5012-E0318

TLE5012-E0742

GMR-Based Angular Sensor  
for Rotor Position Sensing

Target  
Data Sheet

V 0.46

Sensors



Never stop thinking

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# 1 Product Description

## 1.1 Overview

The TLE5012 is a 360° angle sensor that detects the orientation of a magnetic field. This is achieved by measuring sine and cosine angle components with monolithic integrated **Giant Magneto Resistance (IGMR)** elements.

High precision angle values are achieved over temperature and lifetime using internal autocalibration algorithm.

Data communications are accomplished with a bi-directional SSC Interface that is SPI compatible.

The absolute angle value and other values are transmitted via SSC or via a Pulse-Width-Modulation (PWM) Protocol. Also the sine and cosine raw values can be read out. These raw signals are digitally processed internally to calculate the angle orientation of the magnetic field (magnet).

The TLE5012 is a precalibrated sensor. The calibration parameters are stored in laser fuses. At start-up the values of the fuses are written into Flip-Flops, where these values can be changed by the application specific parameters. The TLE5012-E0318 and TLE5012-E0742 are especially configured in a Hall-Switch emulation mode for motors with three or seven pole pairs.

Online diagnostic functions are provided to ensure reliable operation.



Product Type	Marking	Ordering Code	Package
TLE5012	5012	SP000477068	PG-DSO-8
TLE5012-E0318	5012E03	SP000611246	PG-DSO-8
TLE5012-E0742	5012E07	SP000611250	PG-DSO-8

## 1.2 Features

- **Giant Magneto Resistance (GMR)**-based principle
- Integrated magnetic field sensing for angle measurement
- Full calibrated 0 - 360° angle measurement with revolution counter and angle speed measurement
- Two separate highly accurate single bit SD-ADC
- 15 bit representation of absolute angle value on the output (resolution of 0.01°)
- 16 bit representation of sine / cosine values on the interface
- Max. 1.0° angle error over lifetime and temperature with activated auto-calibration
- Bi-directional SSC Interface up to 8Mbit/s
- Supports SIL3 with diagnostic functions and status information
- Interfaces: SSC, PWM, Incremental Interface (IIF), Hall Switch Mode (HSM)
- 0.25 µm CMOS technology
- Automotive qualified: -40°C to 150°C (Junction Temperature)
- ESD > 2kV (HBM)
- Green package with lead-free (Pb-free) plating

## 1.3 Application Example

The TLE5012 GMR-Based Angular Sensor is designed for angular position sensing in automotive applications, such as:

- Electrical Commutated Motor (e.g. used in **Electric Power Steering (EPS)**)
- Rotary Switch
- Steering Angle
- General Angular Sensing



## 2 Functional Description

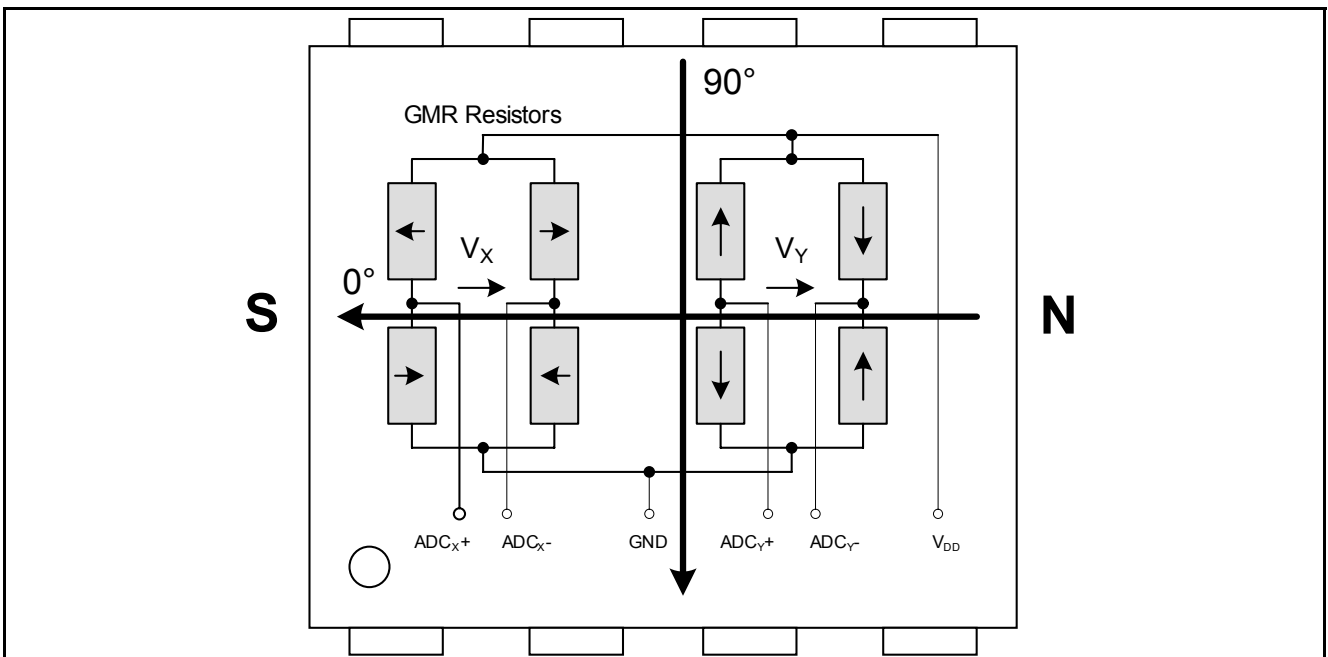
### 2.1 General

The GMR sensor is implemented using vertical integration. This means that the GMR sensitive areas are integrated above the logic portion of the TLE5012 device. These GMR elements change their resistance depending on the direction of the magnetic field.

Four individual GMR elements are connected to one Wheatstone Sensor Bridge. These GMR elements sense one of two components of the applied magnetic field:

- X component,  $V_x$  (cosine) or the
- Y component,  $V_y$  (sine)

The advantage of a full-bridge structure is that the amplitude of the GMR signal is doubled and temperature effects cancel out each other.



**Figure 1 Sensitive Bridges of the GMR Sensor**

*Note: In Figure 1, the arrows in the resistors symbolize the direction of the Reference Layer, which is used for the further explanation.*

The output signal of each bridge is only unambiguous over 180° between two maxima. Therefore two bridges are orientated orthogonally to each other to measure 360°.

With the trigonometric function ARCTAN, the true 360° angle value can be calculated which is represented by the relation of X and Y signals.

Because only the relative values influence the result, the absolute size of the two signals is of minor importance. Therefore, most influences to the amplitudes are compensated.

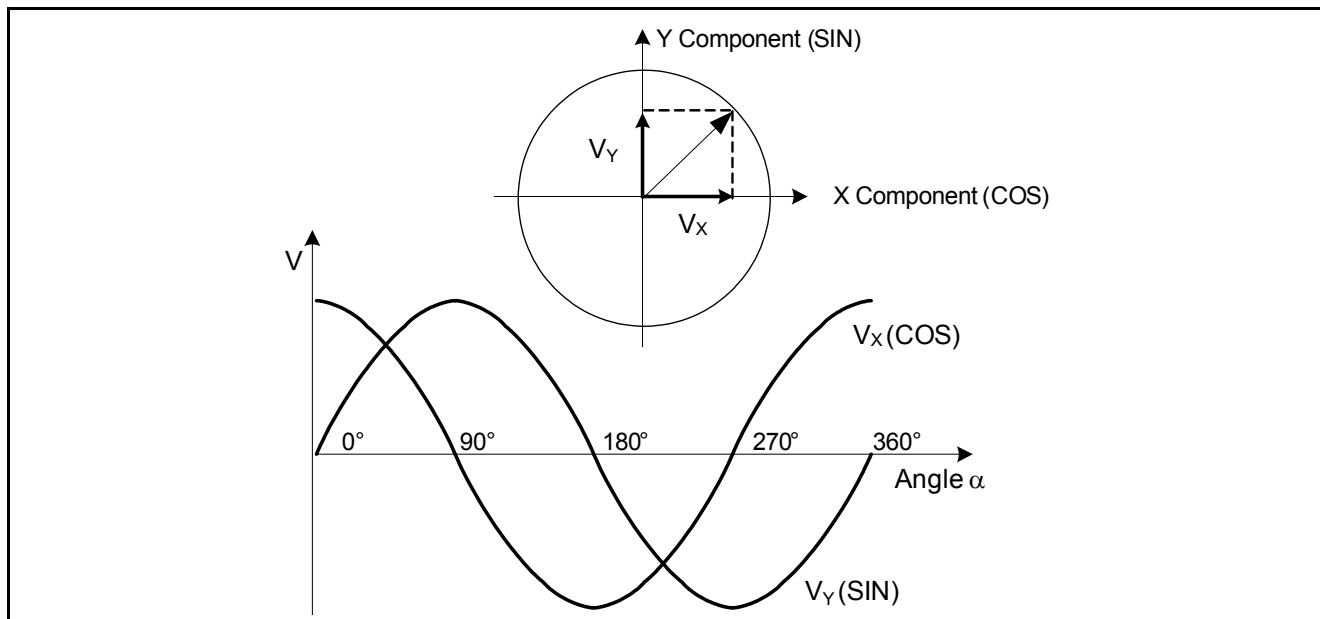


Figure 2 Ideal Output of the GMR Sensor Bridges

## 2.2 Pin Configuration

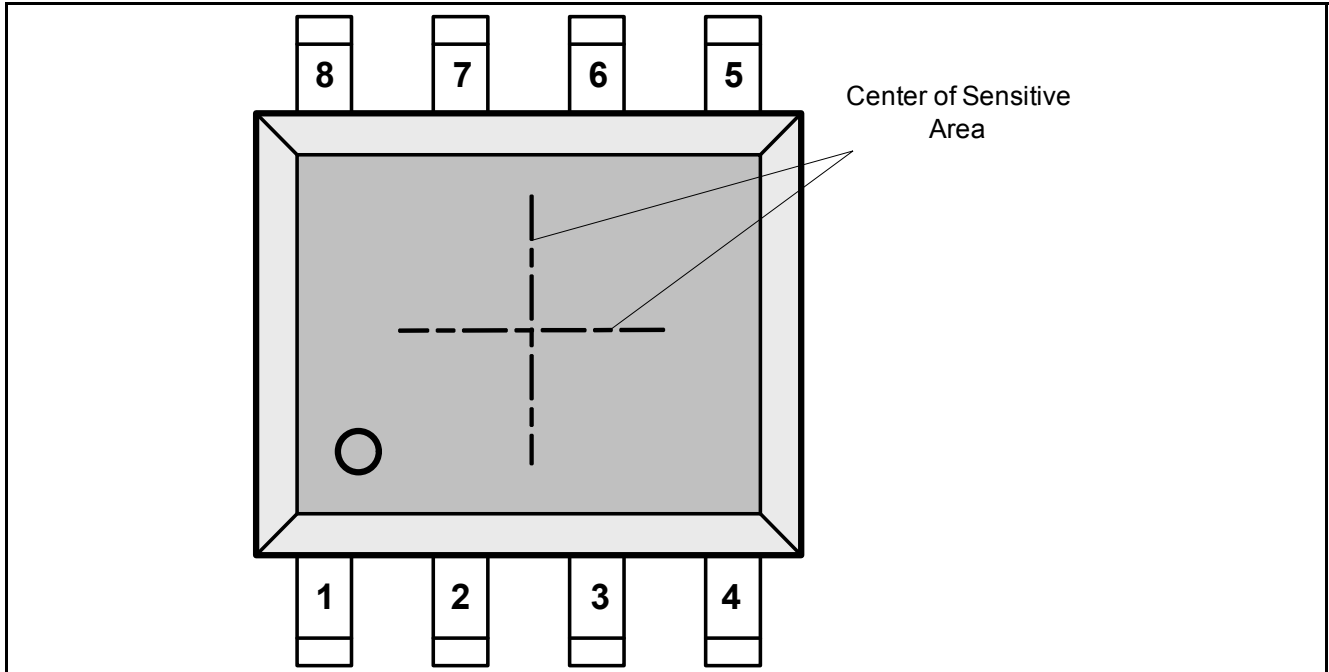


Figure 3 Pin Configuration (Top View)

## 2.3 Pin Description

Table 1 Pin Description

Pin No.	Symbol	In/Out	Function
1	CLK	I	External Clock (must be connected to GND for PWM output)
2	SCK	I	SSC Clock
3	CSQ	I	SSC Chip Select
4	DATA / HS3	I/O	SSC Data / IIF Index / Hall Switch Signal 3
5	IFA (IIF_A / HS1 / PWM)	O	Interface A: IIF Phase A; Hall Switch Signal 1 or PWM output (depends on external application circuit)
6	V <sub>DD</sub>	-	Supply Voltage
7	GND	-	Ground
8	IFB (IIF_B / HS2)	O	Interface B: IIF Phase B or Hall Switch Signal 2

## 2.4 Block Diagram

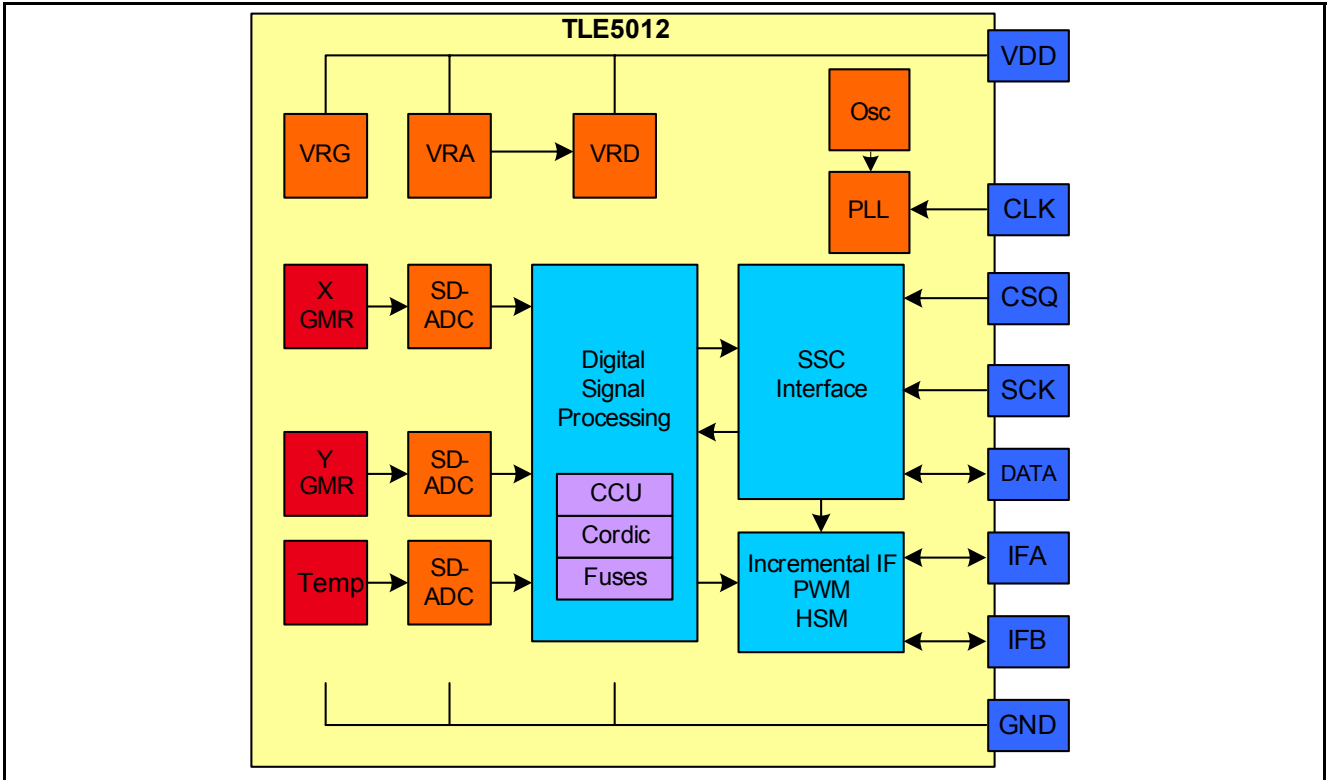


Figure 4 TLE5012 Block Diagram

## 2.5 Functional Block Description

### 2.5.1 Internal Power Supply

The internal stages of the TLE5012 are supplied with different voltage regulators.

- GMR Voltage Regulator VRG
- Analog Voltage Regulator VRA
- Digital Voltage Regulator VRD (derived from VRA)

These regulators are directly connected to the supply voltage  $V_{DD}$ .

### 2.5.2 Oscillator and PLL

The internal frequency oscillator feeds the **Phase Locked Loop (PLL)**. Also the external clock (CLK) can be used therefore.

### 2.5.3 SD-ADC

The SD-ADCs transform the analog GMR-voltages and temperature-voltage into the digital domain.

### 2.5.4 Digital Signal Processing Unit

The Digital Signal Processing Unit (DSPU) contains the:

- **C**apture **C**ompare **U**nit (**CCU**), which is used to generate the PWM signal
- **C**oordinate **R**otation **D**igital **C**omputer (**CORDIC**), which contains the trigonometric function for angle calculation
- Fuses, which contain the calibration parameters

### 2.5.5 Interfaces

Different Interfaces can be selected:

- SSC Interface
- PWM
- Incremental Interface
- Hall Switch Mode

### 2.5.6 Safety Features

The TLE5012 offers a multiplicity on safety features to support Safety Integrity Level (SIL). Sensors with this performance are identified by the following logo:



**Figure 5 PRO-SIL™ Logo**

Safety features are:

- Test vectors switchable to ADC- input
- Inversion or combination of filter input streams
- Data transmission check via 8bit **C**yclic **R**edundancy **C**heck (**CRC**)
- Self test routines
- Two independent active interfaces possible
- Overvoltage and undervoltage detection

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SIL Supporting Features are intended to support the overall System Design to reach the desired SIL (according to IEC61508) or A-SIL (according to ISO26262) level for the Safety System with high efficiency.

SIL respectively A-SIL certification for such a System has to be reached on system level by the System Responsible at an accredited Certification Authority.

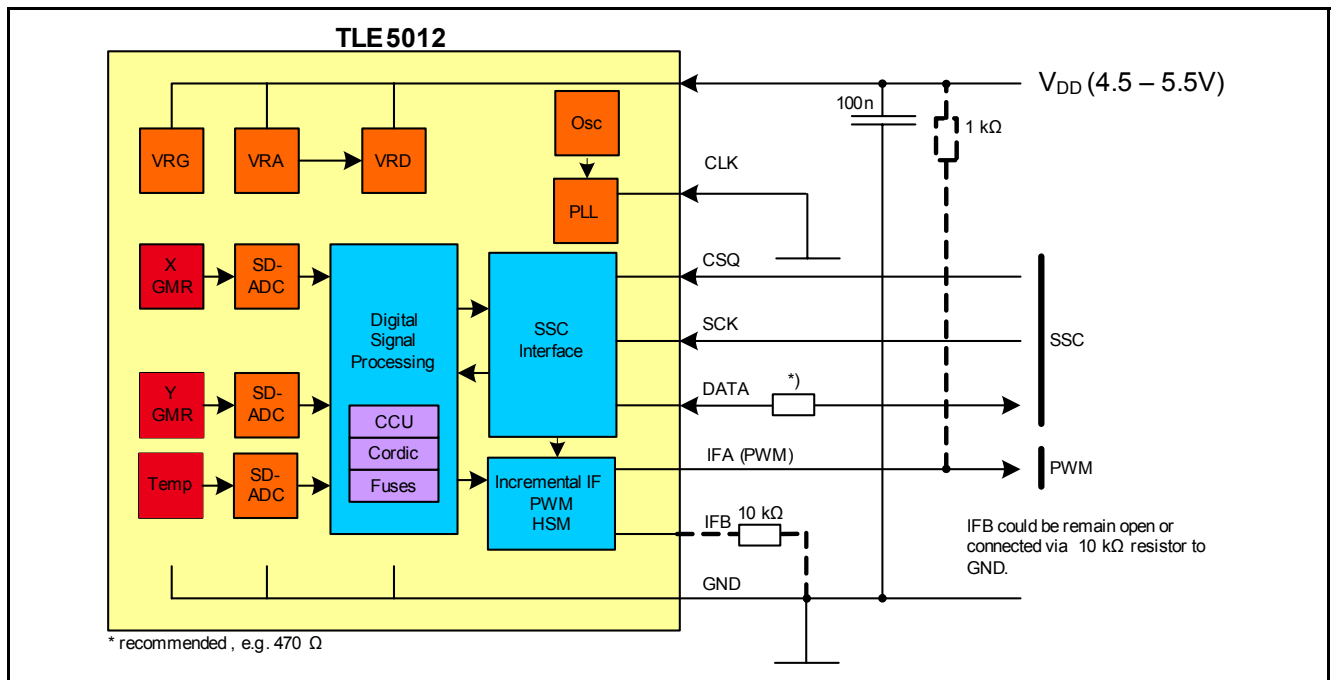
SIL stands for Safety Integrity Level (according to IEC 61508)

A-SIL stands for Automotive-Safety Integrity Level (according to ISO 26262)

### 3 Specification

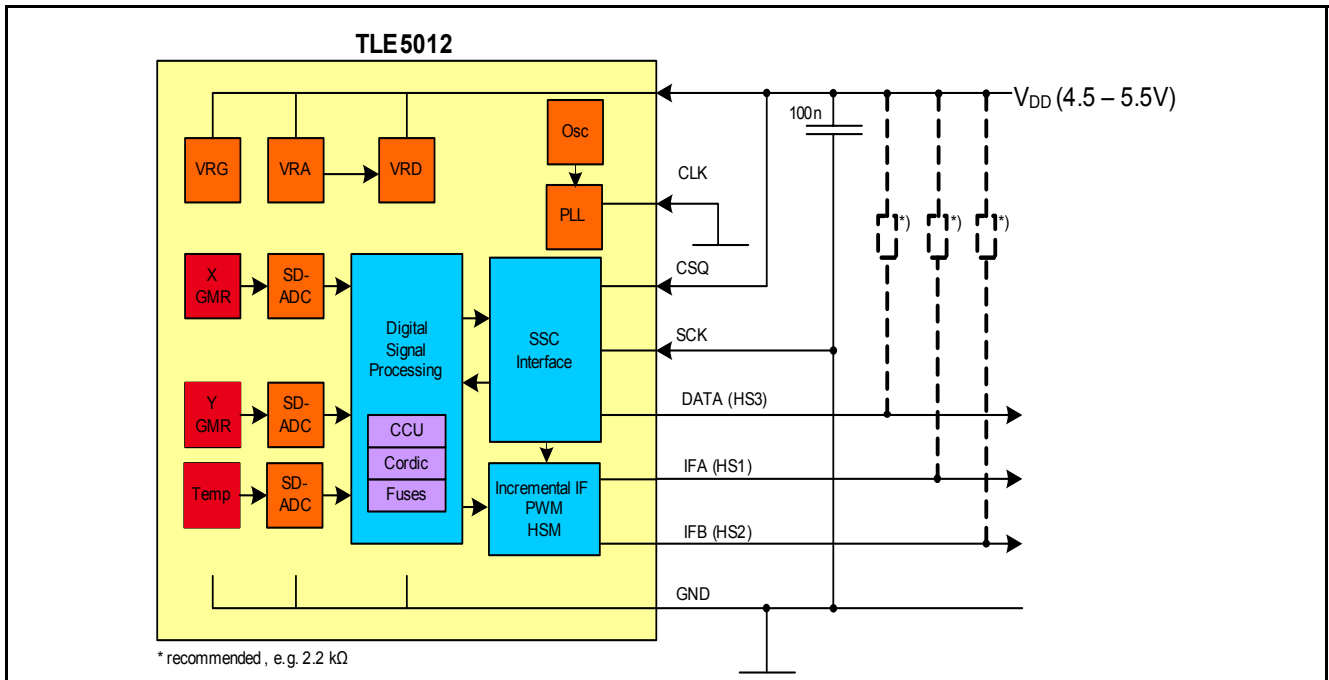
#### 3.1 Application Circuit

The application circuit in [Figure 6](#), [Figure 7](#), [Figure 8](#) and [Figure 9](#) show the different communication possibilities of TLE5012.



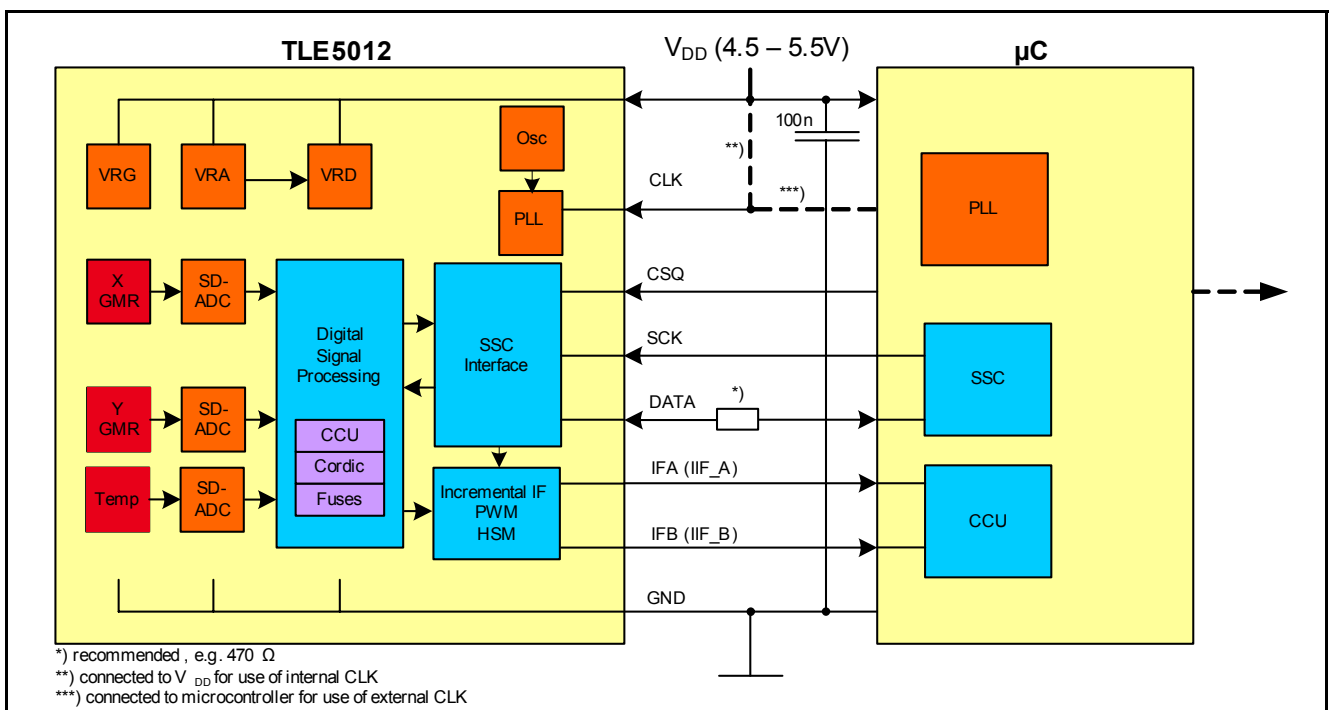
**Figure 6 Application Circuit for TLE5012 with SSC and PWM Interface (using internal CLK)**

**Figure 6** shows a basic block-diagram of the TLE5012 with PWM- Interface. This interface is selectable by connecting CLK to GND. Additionally to the PWM the SSC Interface could be used. Within the SSC- Interface the PWM mode is selectable between Push-Pull and Open Drain.



**Figure 7 Application Circuit for TLE5012 with HS Mode (using internal CLK)**

**Figure 7** shows a basic block-diagram of the TLE5012 with HS Mode. This interface is selectable by connecting CLK to GND and CSQ to  $V_{DD}$ . Additionally to the HSM the SSC Interface could be used by pulling CSQ to GND. Within the SSC- Interface the HS Mode is selectable between Push-Pull and Open Drain.



**Figure 8 Application Circuit for TLE5012 with SSC and IIF Interface (using external CLK)**

**Figure 8** shows a basic block-diagram of an angle sensor system using a TLE5012 and a microcontroller for rotor positioning applications. The depicted Interface-Configuration is needed for High-Speed applications like electrical commutated motor drives. It is possible to connect the TLE5012 to a microcontroller via Incremental Interface and for safety reasons also via SSC-Interface.

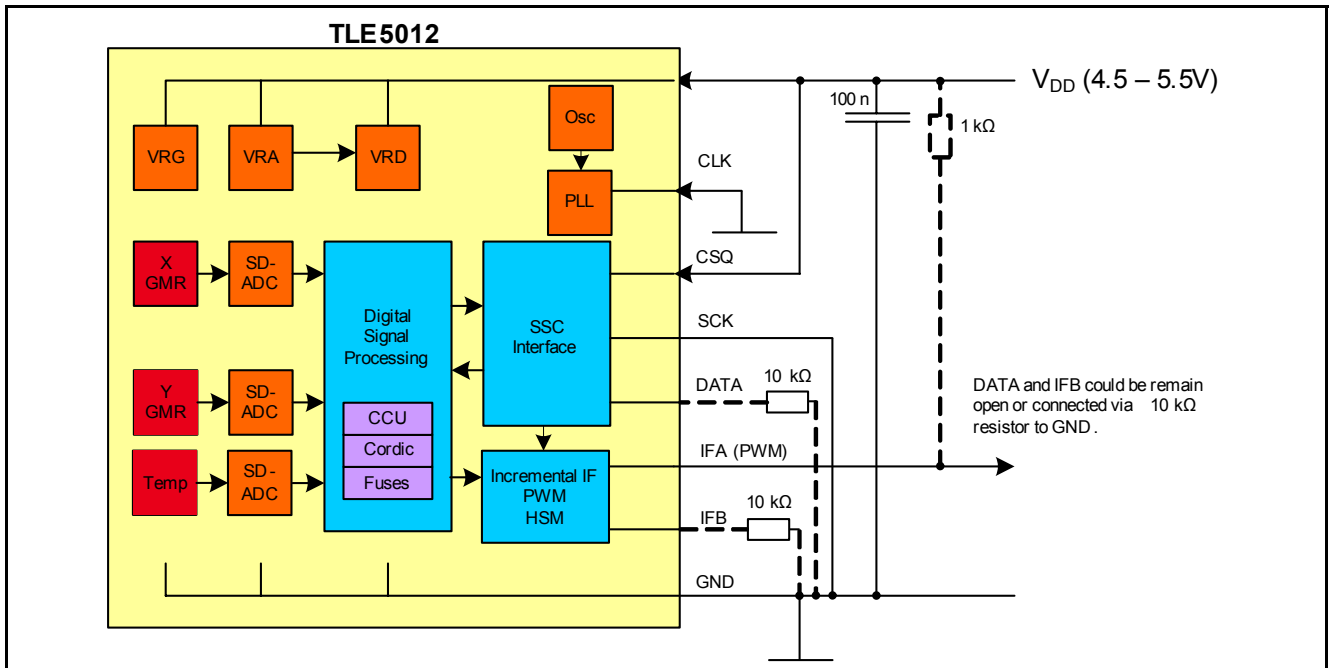


Figure 9 Application Circuit for TLE5012 with only PWM Interface (using internal CLK)



### 3.2 Absolute Maximum Ratings

**Table 2 Absolute Maximum Ratings**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Voltage on $V_{DD}$ pin respect to ground ( $V_{SS}$ )	$V_{DD}$	-0.5	-	6.5	V	max 40 h/Lifetime
Voltage on any pin respect to ground ( $V_{SS}$ )	$V_{IN}$	-0.5	-	6.5	V	additionally $V_{DD} + 0.5$ V may not be exceeded
Junction Temperature	$T_J$	-40	-	150	°C	
		-	-	150	°C	for 1000h not additive
Magnetic Field Induction	B	-	-	125	mT	max. 5 min @ $t_A = 25^\circ\text{C}$
		-	-	100	mT	max. 5 h @ $t_A = 25^\circ\text{C}$
		-	-	70	mT	max. 1000h @ $t_A = 85^\circ\text{C}$ ; not additive
		-	-	60	mT	max. 1000h @ $t_A = 100^\circ\text{C}$ ; not additive
Storage Temperature	$T_{ST}$	-40	-	150	°C	without magnetic field

**Attention: Stresses above the max. values listed here may cause permanent damage to the device. Exposure to absolute maximum rating conditions for extended periods may affect device reliability. Maximum ratings are absolute ratings; exceeding only one of these values may cause irreversible damage to the device.**

### 3.3 Operating Range

The following operating conditions must not be exceeded in order to ensure correct operation of the TLE5012. All parameters specified in the following sections refer to these operating conditions, unless otherwise noticed. **Table 3** is valid for  $-40^\circ\text{C} < T_J < 150^\circ\text{C}$ .

**Table 3 Operating Range**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Supply Voltage	$V_{DD}$	4.5	5.0	5.5	V	<sup>1)</sup>
Output Current (DATA-Pad)	$I_Q$	-	-	-25	mA	PAD_DRV = '0x', sink current <sup>2)</sup>
		-	-	-5	mA	PAD_DRV = '10', sink current <sup>2)</sup>
		-	-	-0.4	mA	PAD_DRV = '11', sink current <sup>2)</sup>
Output Current (IFA / IFB-Pad)	$I_Q$	-	-	-15	mA	PAD_DRV = '0x', sink current <sup>2)</sup>
		-	-	-5	mA	PAD_DRV = '1x', sink current <sup>2)</sup>
Input Voltage	$V_{IN}$	-0.3	-	5.5	V	$V_{DD} + 0.3$ V may not be exceeded

**Table 3 Operating Range (cont'd)**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Magnetic Induction	B <sub>XY</sub>	30	-	50	mT	in X/Y direction <sup>3)</sup>
Angle Range	Ang	0	-	360	°	

- 1) Directly blocked with 100nF ceramic capacitor
- 2) Max. current to GND over Open Drain Output
- 3) Values refer to an homogenous magnetic field (B<sub>XY</sub>) without vertical magnetic induction (B<sub>Z</sub> = 0mT).

Note: The thermal resistances listed in **Table 20 “Package Parameters” on Page 55** must be used to calculate the corresponding ambient temperature.

**Calculation of the Junction Temperature**

The total power dissipation PTOT of the chip increases its temperature above the ambient temperature.

The power multiplied by the total thermal resistance RthJA (Junction to Ambient) leads to the final junction temperature. RthJA is the sum of the addition of the values of the two components Junction to Case and Case to Ambient.

$$R_{thJA} = R_{thJC} + R_{thCA} \tag{1}$$

$$T_J = T_A + \Delta T$$

$$\Delta T = R_{thJA} \times P_{TOT} = R_{thJA} \times (V_{DD} \times I_{DD} + V_{OUT} \times I_{OUT}) \quad (I_{DD}, I_{OUT} > 0, \text{ if direction is into IC})$$

Example (assuming no load on V<sub>out</sub>):

$$V_{DD} = 5V \tag{2}$$

$$I_{DD} = 12mA$$

$$\Delta T = 150 \left[ \frac{K}{W} \right] \times 5[V] \times 0.012[A] + 0[VA] = 9K$$

For moulded sensors, the calculation with RthJC is more adequate.

### 3.4 Characteristics

#### 3.4.1 Electrical Parameters

The indicated electrical parameters apply to the full operating range, unless otherwise specified. The typical values correspond to a supply voltage  $V_{DD} = 5.0\text{ V}$  and  $25\text{ }^\circ\text{C}$ , unless individually specified. All other values correspond to  $-40\text{ }^\circ\text{C} < T_J < 150\text{ }^\circ\text{C}$ .

**Table 4 Electrical Parameters**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Supply Current	$I_{DD}$	-	12	13	mA	
POR Level	$V_{POR}$	2.0	-	2.9	V	Power On Reset
POR Hysteresis	$V_{PORhy}$	-	30	-	mV	
Power On Time	$t_{Pon}$	-	4	5	ms	$V_{DD} > V_{DDmin}^{1)}$
Input Signal Low Level	$V_L$	-	-	$0.3 V_{DD}$	V	
Input Signal High Level	$V_H$	$0.7 V_{DD}$	-	-	V	
Pull-Up Current	$I_{PU}$	-10	-	-225	$\mu\text{A}$	CSQ
		-10	-	-150	$\mu\text{A}$	DATA
Pull-Down Current	$I_{PD}$	10	-	225	$\mu\text{A}$	SCK
		10	-	150	$\mu\text{A}$	CLK, IFA, IFB
Output Signal Low Level	$V_{OL}$	-	-	1	V	DATA; $I_Q = -25\text{ mA}$ (PAD_DRV='0x'), $I_Q = -5\text{ mA}$ (PAD_DRV='10'), $I_Q = -0.4\text{ mA}$ (PAD_DRV='11')
		-	-	1	V	IFA,IFB; $I_Q = -15\text{ mA}$ (PAD_DRV='0x'), $I_Q = -5\text{ mA}$ (PAD_DRV='1x')

1) Within "Power On Time" write access is not permitted

#### 3.4.2 ESD Protection

**Table 5 ESD Protection**

Parameter	Symbol	Values		Unit	Notes
		min.	max.		
ESD Voltage	$V_{HBM}$	-	$\pm 2.0$	kV	Human Body Model <sup>1)</sup>
	$V_{SDM}$	-	$\pm 0.5$	kV	Socketed Device Model <sup>2)</sup>

1) Human Body Model (HBM) according to: JEDEC EIA/JESD22-A114-B

2) Socketed Device Model (SDM) according to: ESD ASS.STD.DS5.3-93

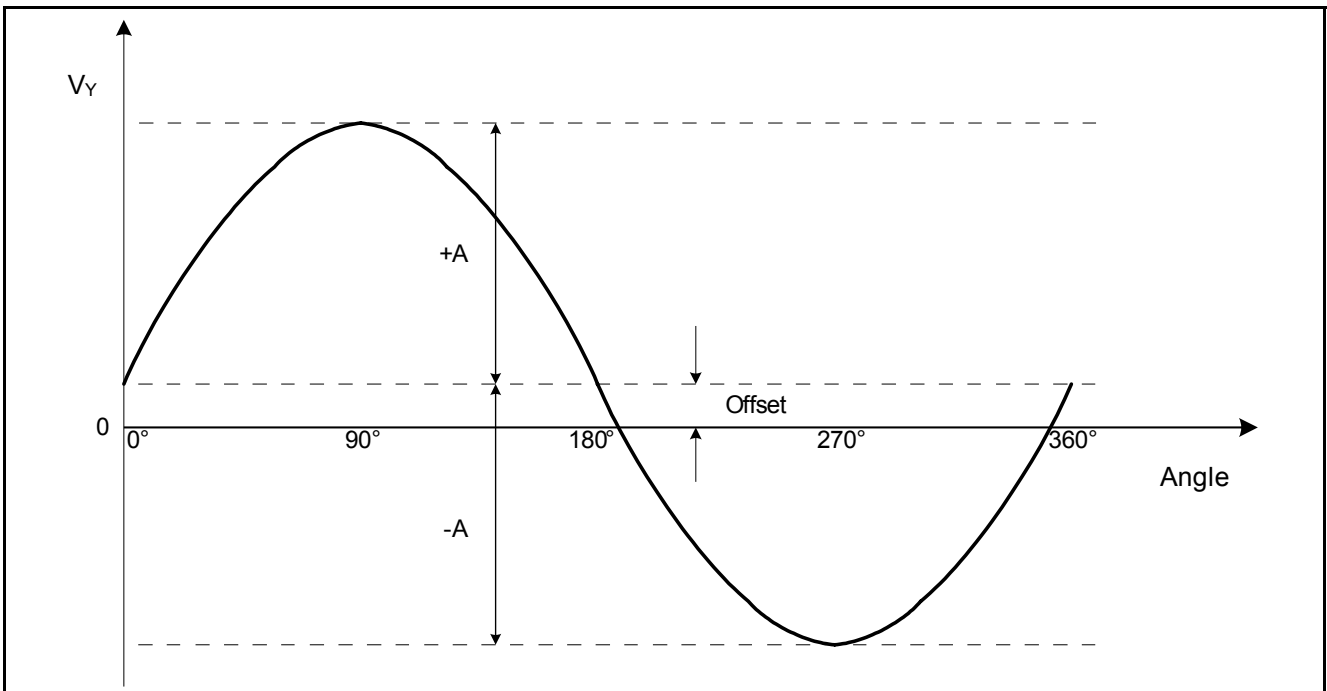
### 3.4.3 GMR Parameters

All parameters apply over the full operating range, unless otherwise specified.

**Table 6 Basic GMR Parameters**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
X, Y output range	$RG_{ADC}$	-	-	$\pm 23230$	digits	
X, Y amplitude <sup>1)</sup>	$A_X, A_Y$	6000	9500	15781	digits	at calibration conditions
		3922	-	20620	digits	operating range
X, Y synchronism <sup>2)</sup>	k	87.5	100	112.49	%	at calibration conditions
X, Y offset <sup>3)</sup>	$O_X, O_Y$	-2048	0	+2047	digits	at calibration conditions
X, Y orthogonality error	$\varphi$	-11.25	0	+11.24	°	at calibration conditions
X, Y without field	$X_0, Y_0$	-5000	-	+5000	digits	without magnet <sup>4)</sup>

- 1) see [Figure 10](#)
- 2)  $k = 100 \cdot (A_X / A_Y)$
- 3)  $O_Y = (Y_{MAX} + Y_{MIN}) / 2$ ;  $O_X = (X_{MAX} + X_{MIN}) / 2$
- 4) Not tested



**Figure 10 Offset and Amplitude Definition**

### 3.4.4 Angle Performance

After internal calculation the sensor has a remaining error, as shown in [Table 7](#). The error value refers to  $B_z = 0\text{mT}$  and the operating conditions given in [Table 3 “Operating Range” on Page 17](#).

The overall angle error represents the relative angle error. This error describes the deviation to the reference line after zero angle definition.

**Table 7 Angle Performance**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Overall Angle Error (with auto-calibration)	$\alpha_{Err}$	-	0.6 <sup>1)</sup>	1.0	°	including lifetime and temperature drift <sup>2)3)</sup>
Overall Angle Error (without auto-calibration)	$\alpha_{Err}$	-	0.6 <sup>1)</sup>	1.6	°	including temperature drift <sup>2)3)</sup>

1) At 25°C, B = 30 mT

2) Including hysteresis error, caused by revolution direction change.

3) Only with calibrated GMR-compensation parameters of customer setup; Relative error after zero angle definition.

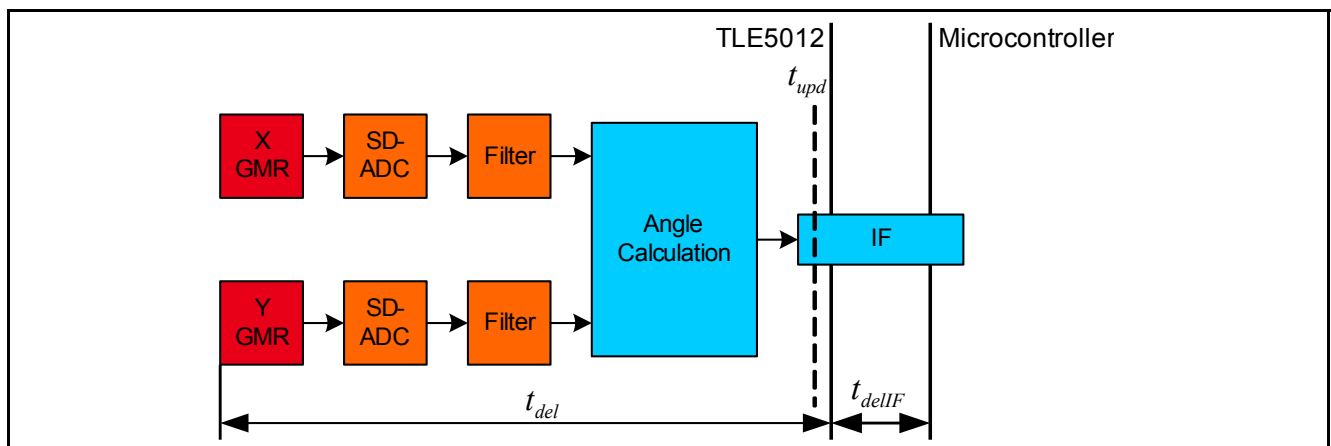
### Autocalibration

The autocalibration enables online parameter calculation and reduces therefore the angle error due to misalignments.

After start-up the parameters out of the fuses get loaded into flip-flops. The TLE5012 updates these parameters after a full revolution. The update can be chosen within the Autocalibration Mode (AUTOCAL) bit. It is possible to do the update after every 22.5°, 11.25° or after  $t_{upd}$ .

### 3.4.5 Signal Processing

The signal path of the TLE5012 is depicted in [Figure 11](#). It consists of the GMR-bridge, ADC, filter and angle calculation. Depending on the filter configuration a different total delay time is achieved. Additional to this delay time, the delay time of the interface has to be considered. The delay time leads to an additional angle error at higher speeds. With enabling the prediction, the signal delay time will be reduced ([Figure 12](#)).



**Figure 11 TLE5012 Signal path**

At FIR\_MD = 0 only raw values can be read out, due to the more time consuming angle calculation.

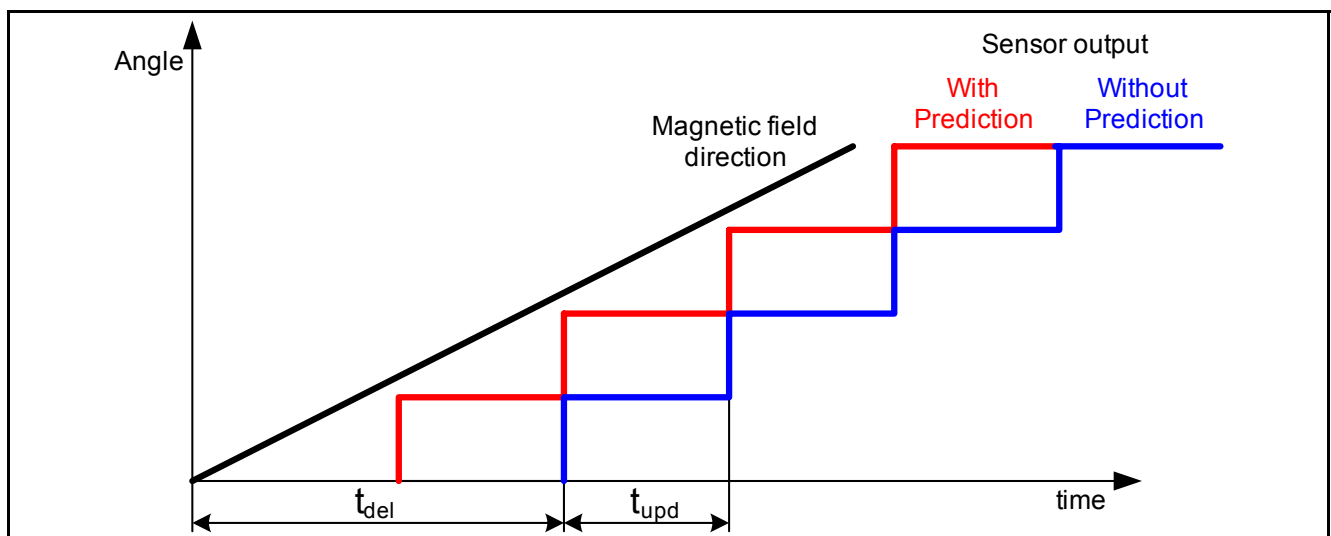
**Table 8 Signal Processing**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Update Rate at Interface	$t_{\text{upd}}$	-	21.3	-	$\mu\text{s}$	FIR_MD = 0 (only raw values) <sup>1)2)</sup>
		-	42.7	-	$\mu\text{s}$	FIR_MD = 1 <sup>1)2)</sup>
		-	85.3	-	$\mu\text{s}$	FIR_MD = 2 (default) <sup>1)2)</sup>
		-	170.6	-	$\mu\text{s}$	FIR_MD = 3 <sup>1)2)</sup>
Angle Delay Time <sup>3)</sup>	$t_{\text{del}}$	-	60	70	$\mu\text{s}$	FIR_MD = 1 <sup>1)2)</sup>
		-	80	95	$\mu\text{s}$	FIR_MD = 2 <sup>1)2)</sup>
		-	120	140	$\mu\text{s}$	FIR_MD = 3 <sup>1)2)</sup>
Angle Delay Time with Prediction <sup>3)</sup>	$t_{\text{del}}$	-	20	30	$\mu\text{s}$	FIR_MD = 1; PREDICT = 1 <sup>1)2)</sup>
		-	5	20	$\mu\text{s}$	FIR_MD = 2; PREDICT = 1 <sup>1)2)</sup>
		-	-40	-20	$\mu\text{s}$	FIR_MD = 3; PREDICT = 1 <sup>1)2)</sup>
Angle Noise	$N_{\text{Angle}}$	-	0.11	-	$^{\circ}$	FIR_MD = 0, (1 Sigma) <sup>2)</sup>
		-	0.08	-	$^{\circ}$	FIR_MD = 1, (1 Sigma) <sup>2)</sup>
		-	0.05	-	$^{\circ}$	FIR_MD = 2, (1 Sigma) <sup>2)</sup> (default)
		-	0.04	-	$^{\circ}$	FIR_MD = 3, (1 Sigma) <sup>2)</sup>

1) depends on internal oscillator frequency variation ([Chapter 3.4.6](#))

2) guaranteed by laboratory characterization

3) valid at constant rotation speed



**Figure 12 Delay of Sensor Output**

### 3.4.6 Clock Supply (CLK Timing Definition)

If the external clock supply is selected, the clock signal input 'CLK' must fulfill certain requirements which are described in the following:

- The high or low pulse width must not exceed the specified values, because the PLL needs a minimum pulse width and must be spike filtered.
- The duty cycle factor should be 0.5 but can deviate to the values limited by  $t_{CLKh(f_{min})}$  and  $t_{CLKl(f_{min})}$ .
- The PLL is triggered at the positive edge of the clock. If more than 2 edges are missing, a chip reset is generated automatically.

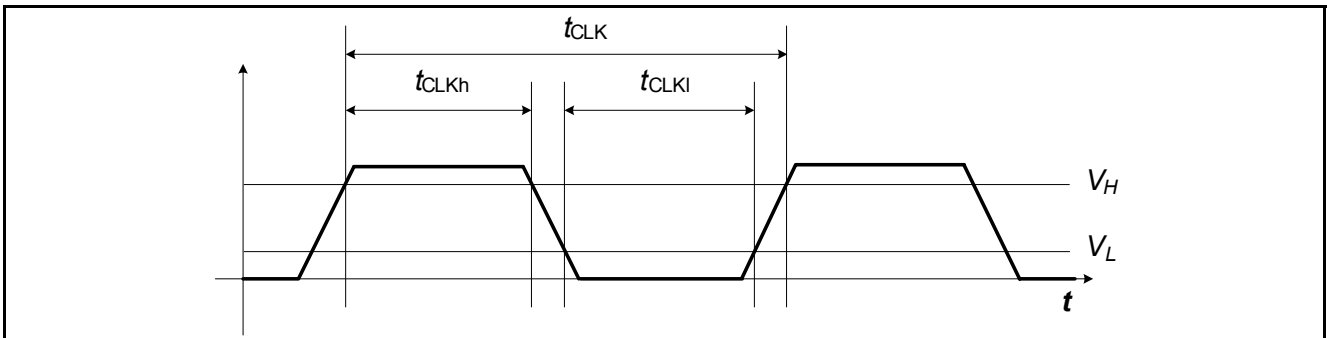


Figure 13 External CLK Timing Definition

Table 9 CLK Timing Specification

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Input Frequency	$f_{CLK}$	3.8	4.0	4.2	MHz	
CLK Duty Cycle <sup>1)2)</sup>	$CLK_{DUTY}$	30	50	70	%	
CLK Rise Time	$t_{CLKr}$	-	-	30	ns	from $V_L$ to $V_H$
CLK Fall Time	$t_{CLKf}$	-	-	30	ns	from $V_H$ to $V_L$
Digital Clock	$f_{DIG}$	22.8	24	25.2	MHz	
Internal Oscillator Frequency	$f_{CLK}$	3.8	4.0	4.2	MHz	

1) Minimum Duty Cycle Factor:  $t_{CLKh(f_{min})} / t_{CLK(f_{min})}$  with  $t_{CLK(f_{min})} = 1 / f_{CLK(f_{min})}$

2) Maximum Duty Cycle Factor:  $t_{CLKh(f_{max})} / t_{CLK(f_{min})}$  with  $t_{CLKh(f_{max})} = t_{CLK(f_{min})} - t_{CLKl(min)}$

### 3.5 Interfaces

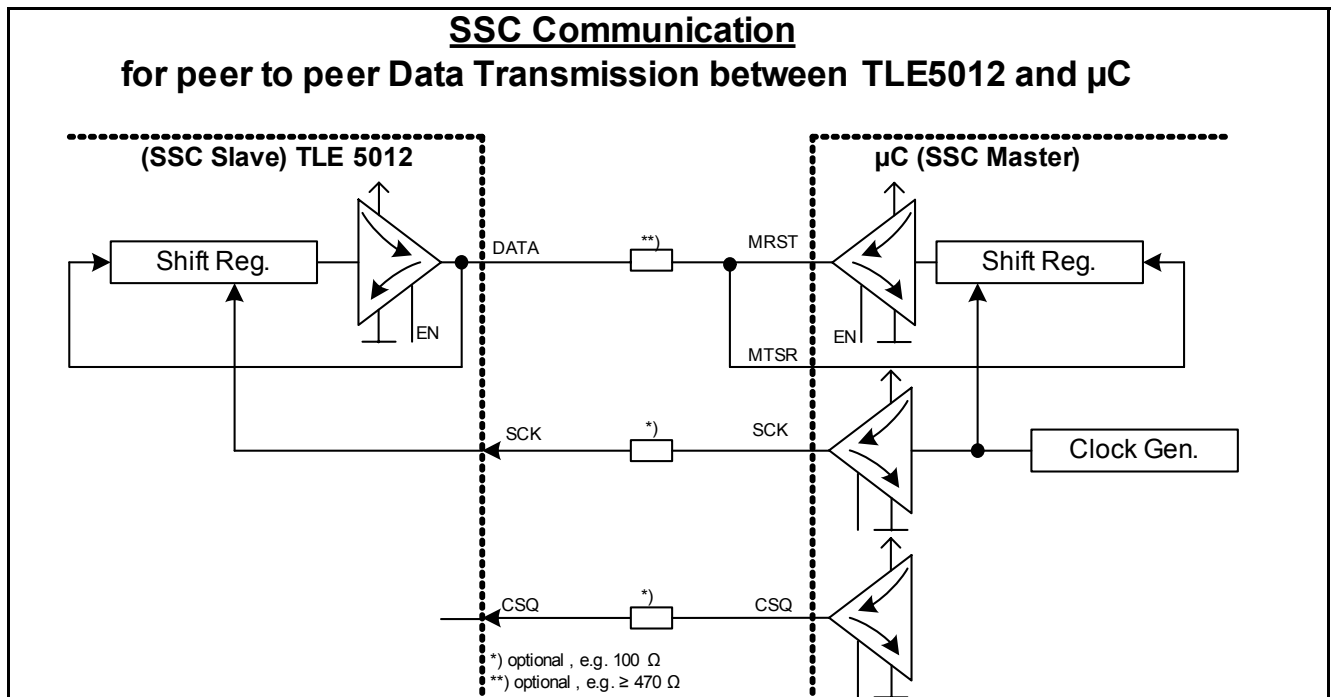
Within the register MOD\_3, the driver strength and so the slope can be varied of the sensor output. The driver strength is specified in [Table 3](#) and the slope fall and rise time in [Table 10](#).

**Table 10 PAD Characteristic**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Output Fall Time	$t_{fall}, t_{rise}$	-	-	8	ns	DATA, 50pF, PAD_DRV='00'
Output Rise Time		-	-	28	ns	DATA, 50pF, PAD_DRV='01'
		-	-	45	ns	DATA, 50pF, PAD_DRV='10'
		-	-	130	ns	DATA, 20pF, PAD_DRV='11'
		-	-	10	ns	IFA/IFB, 20pF, PAD_DRV='0x'
		-	-	tbd	ns	IFA/IFB, 20pF, PAD_DRV='1x'

#### 3.5.1 Synchronous Serial Communication (SSC) Interface

The 3-pin SSC Interface has a bi-directional push-pull data line, serial clock signal and chip select. The SSC Interface is designed to communicate with a microcontroller peer to peer for fast applications.



**Figure 14 SSC Configuration in Sensor-Slave Mode with Push-Pull Outputs (High Speed Application)**



Another possibility is a 3-pin SSC Interface with bidirectional open-drain data line, serial clock signal and chip select. This setup is designed to communicate with a microcontroller in a bus system, together with other SSC slaves (e.g. two TLE5012 for redundancy reasons). This mode can be activated using bit SSC\_OD.

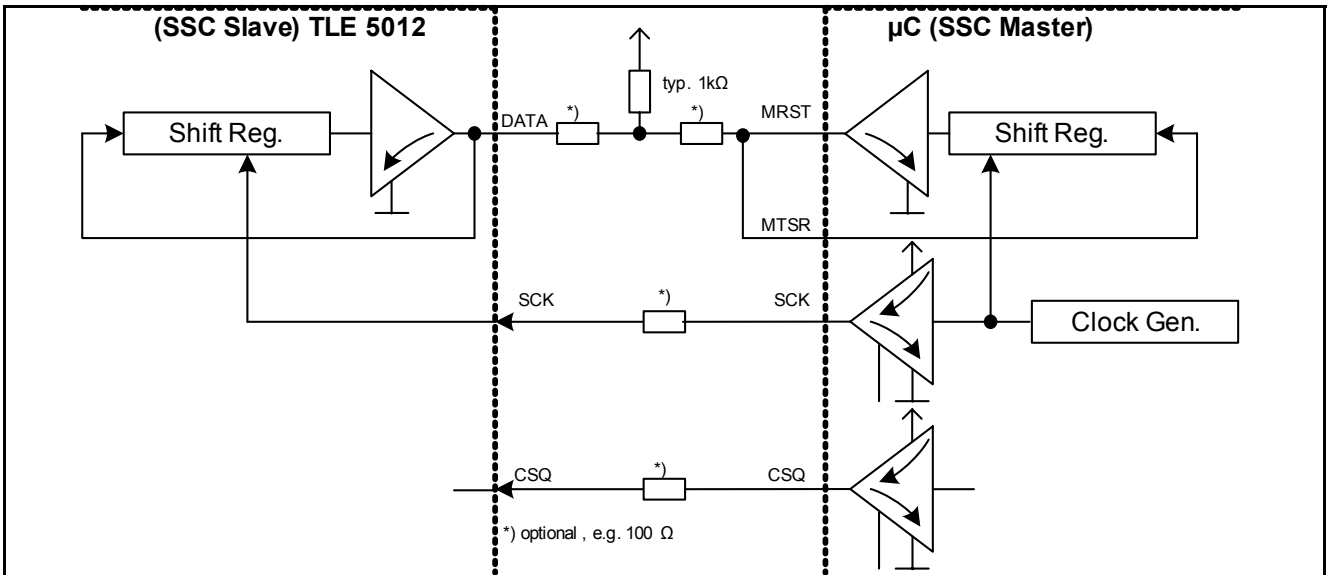


Figure 15 SSC Configuration in Sensor-Slave Mode and Open Drain (Safe Bus Systems)

### 3.5.1.1 SSC Timing Definition

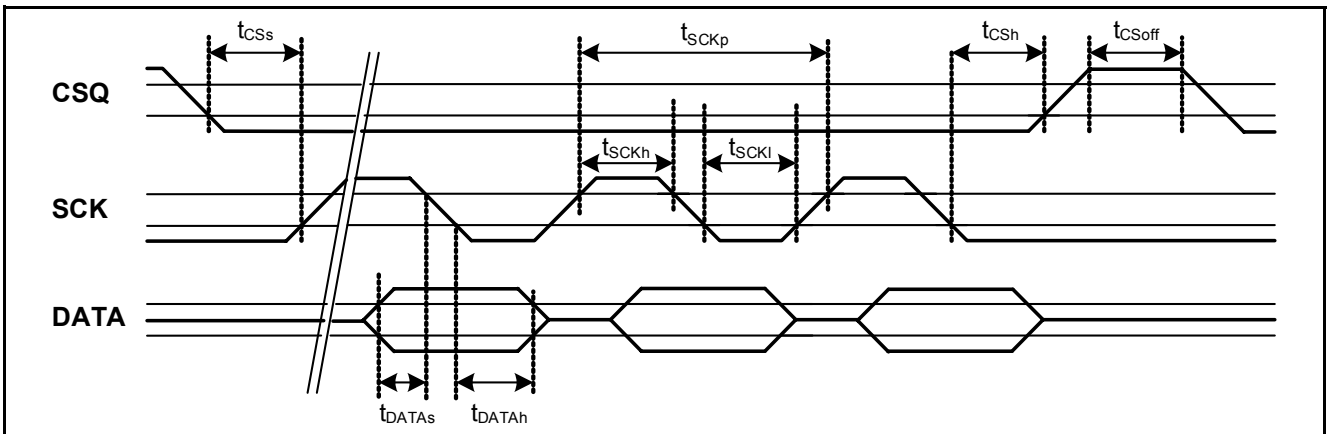


Figure 16 SSC Timing

#### SSC Inactive Time (CS<sub>off</sub>)

The SSC inactive time defines the delay time after a transfer before the TLE5012 can be selected again.

Table 11 SSC Push-Pull Timing Specification

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
SSC Baud Rate	$f_{SSC}$	-	8.0	-	Mbit/s	
CSQ Setup Time	$t_{CSS}$	105	-	-	ns	
CSQ Hold Time	$t_{CSh}$	105	-	-	ns	

**Table 11 SSC Push-Pull Timing Specification (cont'd)**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
CSQ off	$t_{CSoff}$	600	-	-	ns	SSC inactive time
SCK Period	$t_{SCKp}$	120	125	-	ns	
SCK High	$t_{SCKh}$	40	-	-	ns	
SCK Low	$t_{SCKl}$	30	-	-	ns	
DATA Setup Time	$t_{DATA_s}$	25	-	-	ns	
DATA Hold Time	$t_{DATA_h}$	40	-	-	ns	
Write Read Delay	$t_{wr\_delay}$	130	-	-	ns	

**Table 12 SSC Open Drain Timing Specification**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
SSC Baud Rate	$f_{SSC}$	-	2.0	-	Mbit/s	Pull-up Resistor = 1k $\Omega$
CSQ Setup Time	$t_{CS_s}$	300	-	-	ns	
CSQ Hold Time	$t_{CS_h}$	400	-	-	ns	
CSQ off	$t_{CSoff}$	600	-	-	ns	SSC inactive time
SCK Period	$t_{SCKp}$	500	-	-	ns	
SCK High	$t_{SCKh}$	-	190	-	ns	
SCK Low	$t_{SCKl}$	-	190	-	ns	
DATA Setup Time	$t_{DATA_s}$	25	-	-	ns	
DATA Hold Time	$t_{DATA_h}$	40	-	-	ns	
Write Read Delay	$t_{wr\_delay}$	130	-	-	ns	

### 3.5.1.2 SSC Data Transfer

The SSC data transfer is word aligned. The following transfer words are possible:

- Command word (to access and change operating modes of the TLE5012)
- Data words (any data transferred in any direction)
- Safety word (confirms the data transfer and provide status information)

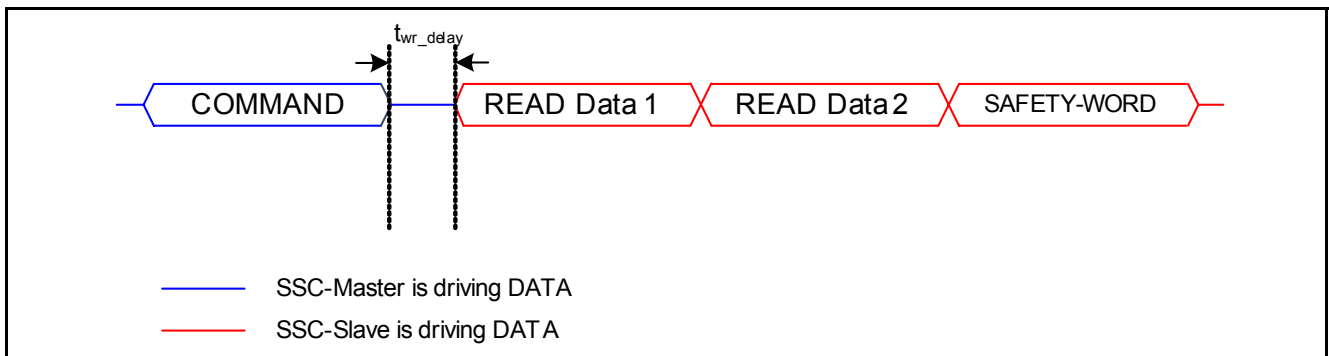


Figure 17 SSC Data Transfer (Data Read Example)

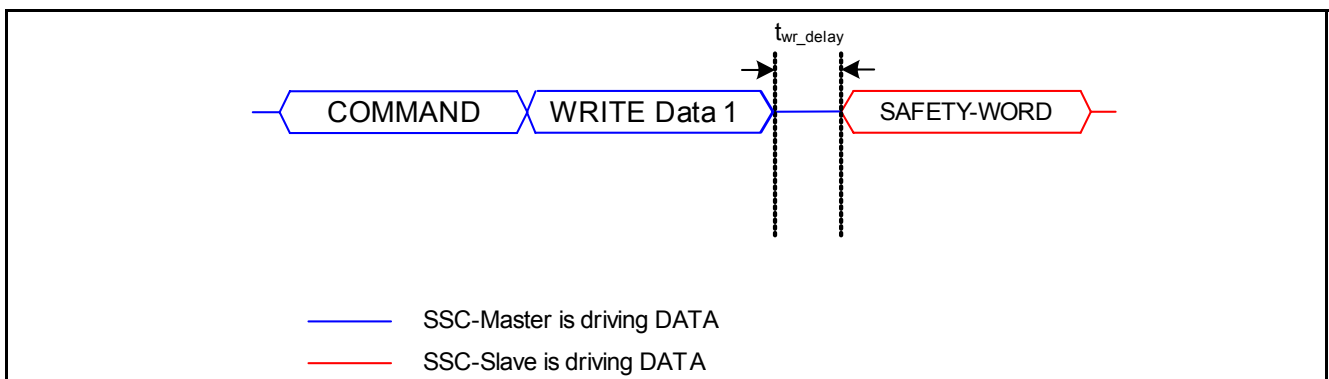


Figure 18 SSC Data Transfer (Data Write Example)

#### Command Word

The TLE5012 is controlled by a command word. It is sent first at every data transmission. The structure of the command word is shown in [Table 13](#), where the UPD-bit allows the access to current values or updated values. If an update command is issued and the update bit (UPD) is set, the immediate values are stored in the update buffer simultaneously. This enables a snapshot of all necessary system parameters at the same time. Bits with an update buffer are marked by an “u” in type of register description. The initialization of such an update is described on page [29](#).

Table 13 Structure of the Command Word

Name	Bits	Description
RW	[15]	Read - Write 0:Write 1:Read
Lock	[14..11]	4 bit Lock Value 0000 <sub>B</sub> : Default Operating Access for addresses 0x00:0x04 1010 <sub>B</sub> : Config- Access for addresses 0x05:0x11

**Table 13 Structure of the Command Word**

Name	Bits	Description
UPD	[10]	Update-Register Access 0: Access to current values 1: Access to updated values
ADDR	[9..4]	6 bit Address
ND	[3..0]	4 bit Number of Data-Words

**Safety Word**

The safety word contains following bits:

**Table 14 Structure of the Safety Word**

Name	Bits	Description
STAT	Chip and Interface Status	
	[15]	Indication of Chip-Reset (resets after readout) via SSC 0: Reset occurred 1: No reset Reset: 1 <sub>B</sub>
	[14]	System Error (e.g. Overvoltage; Undervoltage; V <sub>DD-</sub> , GND- off; ROM;...) 0: Error occurred (S_VR; S_DSPU; S_OV; S_XYOL; S_MAGOL; S_ADCM) 1: No error
	[13]	Interface Access Error (access to wrong address; wrong lock) 0: Error occurred 1: No error
	[12]	Valid Angle Value (no system error; no interface error; NO_GMR_A = '0'; NO_GMR_XY='0') 0: Angle value invalid 1: Angle value valid
RESP	[11..8]	Sensor Number Response Indicator The sensor no. bit is pulled low and the other bits are high.
CRC	[7..0]	Cyclic Redundancy Check (CRC)

Data Communication via SSC

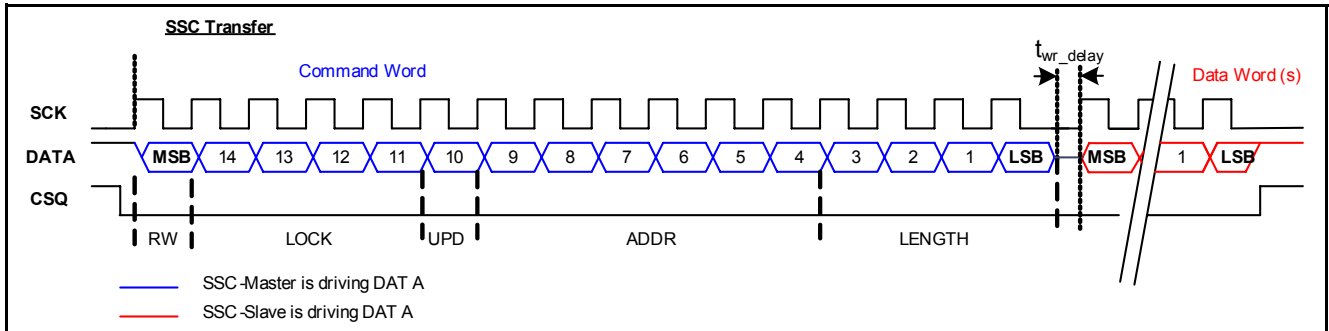


Figure 19 SSC Bit Ordering (Read Example)

The data communication via SSC interface has the following characteristic:

- The data transmission order is “Most Significant Bit (MSB) first”.
- Data is put on the data line with the rising edge on SCK and read with the falling edge on SCK.
- The SSC Interface is word-aligned. All functions are activated after each transmitted word.
- A “high” condition on the negated Chip Select pin (CSQ) of the selected TLE5012 interrupts the transfer immediately. The CRC calculator is automatically reset.
- After changing the data direction, a delay ( $t_{wr\_delay}$ ) has to be considered before continuing the data transfer. This is necessary for internal register access.
- Every access to the TLE5012 with the number of data (ND)  $\geq 1$  is performed with address auto-increment.
- At an overflow at address  $3F_H$  the transfer continuous at address  $00_H$ .
- With ND = 0 no auto-increment is done and a continuously readout of the same address can be realized. Afterwards no Safety Word is send and the transfer ends with high condition on CSQ.
- After every data transfer with ND  $\geq 1$  the 16 bit Safety Word will be appended by the selected TLE5012.
- At a rising edge of CSQ without data transfer before (no SCK-pulse), the update-registers are updated with according values.
- After sending the Safety Word the transfer ends. To start another data transfer, the CSQ has to be deselected once for  $t_{CSoff}$ .
- The SSC is default Push-Pull. The Push-Pull driver is only active, if the TLE5012 has to send data, otherwise the Push-Pull is disabled for receiving data from the microcontroller.

Cyclic Redundancy Check (CRC)

- This CRC is according to the J1850 Bus-Specification.
- Every new transfer resets the CRC generation.
- Every Byte of a transfer will be taken into account to generate the CRC (also the sent command(s)).
- Generator-Polynomial:  $X^8+X^4+X^3+X^2+1$ , but for the CRC generation the fast-CRC generation circuit is used (see Figure 20)
- The remainder of the fast CRC circuit is initial set to '11111111<sub>B</sub>'.
- Remainder is inverted before transmission.

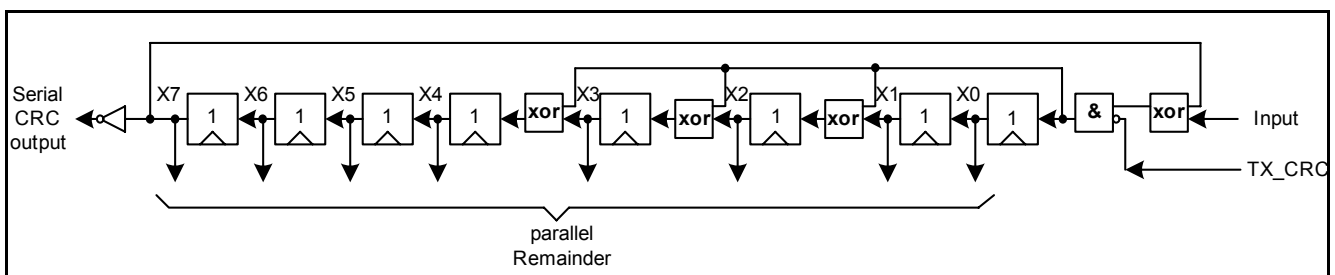


Figure 20 Fast CRC Polynomial Division Circuit

### 3.5.1.3 Registers Chapter

This chapter defines the registers of the TLE5012. It also defines the read/write access rights of the specific registers. **Table 15** identifies the values with symbols. Access to the registers is accomplished via the SSC Interface.

**Table 15 Registers Overview**

Register Short Name	Register Long Name	Offset Address	Page Number
<b>Registers Chapter, TLE5012 Register</b>			
<b>STAT</b>	Status Register	00 <sub>H</sub>	<b>31</b>
<b>ACSTAT</b>	Activation Status Register	01 <sub>H</sub>	<b>33</b>
<b>AVAL</b>	Angle Value Register	02 <sub>H</sub>	<b>34</b>
<b>ASPD</b>	Angle Speed Register	03 <sub>H</sub>	<b>35</b>
<b>AREV</b>	Angle Revolution Register	04 <sub>H</sub>	<b>35</b>
<b>FSYNC</b>	Frame Synchronization Register	05 <sub>H</sub>	<b>36</b>
<b>MOD_1</b>	Interface Mode1 Register	06 <sub>H</sub>	<b>37</b>
<b>SIL</b>	SIL Register	07 <sub>H</sub>	<b>38</b>
<b>MOD_2</b>	Interface Mode2 Register	08 <sub>H</sub>	<b>39</b>
<b>MOD_3</b>	Interface Mode3 Register	09 <sub>H</sub>	<b>40</b>
<b>OFFX</b>	Offset X	0A <sub>H</sub>	<b>41</b>
<b>OFFY</b>	Offset Y	0B <sub>H</sub>	<b>42</b>
<b>SYNCH</b>	Synchronicity	0C <sub>H</sub>	<b>42</b>
<b>IFAB</b>	IFAB Register	0D <sub>H</sub>	<b>43</b>
<b>MOD_4</b>	Interface Mode4 Register	0E <sub>H</sub>	<b>44</b>
<b>TCO_Y</b>	Temperature Coefficient Register	0F <sub>H</sub>	<b>45</b>
<b>ADC_X</b>	X-raw value	10 <sub>H</sub>	<b>45</b>
<b>ADC_Y</b>	Y-raw value	11 <sub>H</sub>	<b>46</b>

The register is addressed wordwise.

### 3.5.1.3.1 TLE5012 Register

#### Status Register

**STAT** **Offset** **Reset Value**  
**Status Register** **00<sub>H</sub>** **8001<sub>H</sub>**

15	14	13	12	11	10	9	8
RD_ST	S_NR		NO_GMR_A	NO_GMR_XY	S_ROM	S_ADCT	Res
r	rw		ru	ru	r	ru	
7	6	5	4	3	2	1	0
S_MAGOL	S_XYOL	S_OV	S_DSPU	S_FUSE	S_VR	S_WD	S_RST
ru	ru	ru	ru	ru	ru	ru	ru

Field	Bits	Type	Description
RD_ST	15	r	<b>Read Status</b> 0 <sub>B</sub> after readout 1 <sub>B</sub> status values changed Reset: 1 <sub>B</sub>
S_NR	14:13	rw	<b>Slave Number</b> is given at startup by the external circuit of IFA and IFB. Reset: 00 <sub>B</sub>
NO_GMR_A	12	ru	<b>No GMR Angle Value</b> 0 <sub>B</sub> valid GMR angle value on the interface 1 <sub>B</sub> no valid GMR angle value on the interface Reset: 0 <sub>B</sub>
NO_GMR_XY	11	ru	<b>No GMR XY Values</b> 0 <sub>B</sub> valid GMR_XY values on the interface 1 <sub>B</sub> no valid GMR_XY values on the interface Reset: 0 <sub>B</sub>
S_ROM	10	r	<b>Status ROM</b> 0 <sub>B</sub> after readout, CRC ok 1 <sub>B</sub> CRC fail or running Reset: 0 <sub>B</sub>
S_ADCT	9	ru	<b>Status ADC-Test</b> 0 <sub>B</sub> after readout 1 <sub>B</sub> Test vectors out of limit Reset: 0 <sub>B</sub>

Field	Bits	Type	Description
S_MAGOL	7	ru	<b>Status Magnitude Out of Limit</b> 0 <sub>B</sub> after readout 1 <sub>B</sub> GMR-magnitude out of limit (>23230 digits) Reset: 0 <sub>B</sub>
S_XYOL	6	ru	<b>Status X,Y Data Out of Limit</b> 0 <sub>B</sub> after readout 1 <sub>B</sub> X,Y data out of limit (>23230 digits) Reset: 0 <sub>B</sub>
S_OV	5	ru	<b>Status Overflow</b> 0 <sub>B</sub> after readout 1 <sub>B</sub> DSPU overflow occurred Reset: 0 <sub>B</sub>
S_DSPU	4	ru	<b>Status Digital Signal Processing Unit</b> 0 <sub>B</sub> after readout 1 <sub>B</sub> DSPU self test not ok, or selftest is running Reset: 0 <sub>B</sub>
S_FUSE	3	ru	<b>Status Fuse CRC</b> 0 <sub>B</sub> after readout, Fuse CRC ok 1 <sub>B</sub> Fuse CRC fail Reset: 0 <sub>B</sub>
S_VR	2	ru	<b>Status Voltage Regulator</b> 0 <sub>B</sub> after readout 1 <sub>B</sub> V <sub>DD</sub> overvoltage; V <sub>DD</sub> undervoltage; V <sub>DD</sub> -off; GND-off; or V <sub>OVG</sub> ; V <sub>OVA</sub> ; V <sub>OVD</sub> too high Reset: 0 <sub>B</sub>
S_WD	1	ru	<b>Status Watchdog</b> 0 <sub>B</sub> after chip reset 1 <sub>B</sub> watchdog counter expired Reset: 0 <sub>B</sub>
S_RST	0	ru	<b>Status Reset</b> 0 <sub>B</sub> after readout 1 <sub>B</sub> indication of power-up, short power-break or active reset Reset: 1 <sub>B</sub>

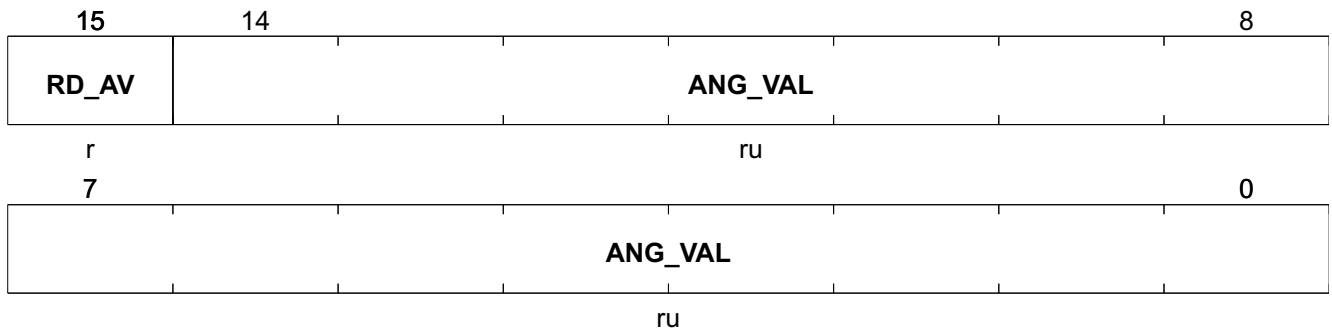




Field	Bits	Type	Description
AS_RST	0	rw	<b>Activation of Hardware Reset</b> Activation occurs after CSQ switches from '0' to '1' after SSC transfer. 0 <sub>B</sub> after execution 1 <sub>B</sub> activation of HW Reset Reset: 0 <sub>B</sub>

**Angle Value Register**

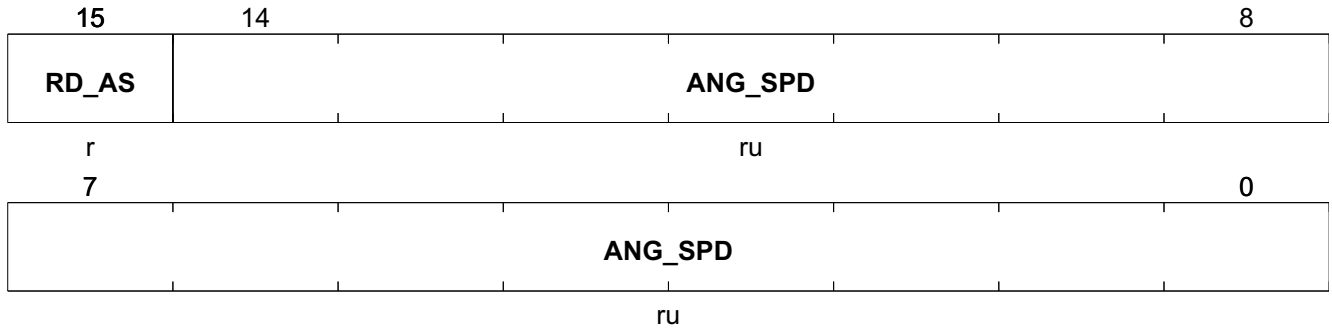
<b>AVAL</b>	<b>Offset</b>	<b>Reset Value</b>
Angle Value Register	02 <sub>H</sub>	8000 <sub>H</sub>



Field	Bits	Type	Description
RD_AV	15	r	<b>Read Status, Angle Value</b> 0 <sub>B</sub> after readout 1 <sub>B</sub> new angle value (ANG_VAL) present Reset: 1 <sub>B</sub>
ANG_VAL	14:0	ru	<b>Calculated Angle Value</b> (ANG_RANGE = 0x080) 4000 <sub>H</sub> -180° 0000 <sub>H</sub> 0° 3FFF <sub>H</sub> +179.99° Reset: 0 <sub>H</sub>

**Angle Speed Register**

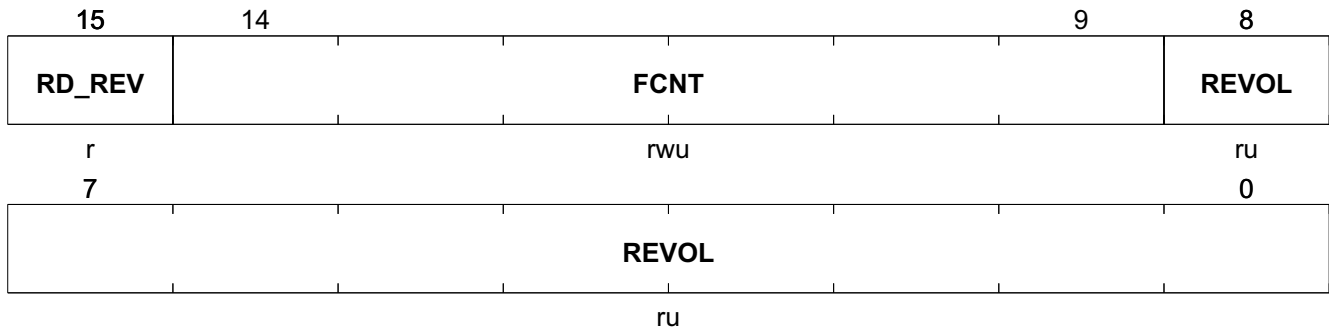
**ASPD** **Offset** **Reset Value**  
**Angle Speed Register** **03<sub>H</sub>** **8000<sub>H</sub>**



Field	Bits	Type	Description
RD_AS	15	r	<b>Read Status, Angle Speed</b> 0 <sub>B</sub> after readout 1 <sub>B</sub> new angle speed value (ANG_SPD) present Reset: 1 <sub>B</sub>
ANG_SPD	14:0	ru	<b>Calculated Angle Speed</b> Without prediction difference between two consecutive angle values. With prediction, difference between three consecutive angle values. Reset: 0 <sub>H</sub>

**Angle Revolution Register**

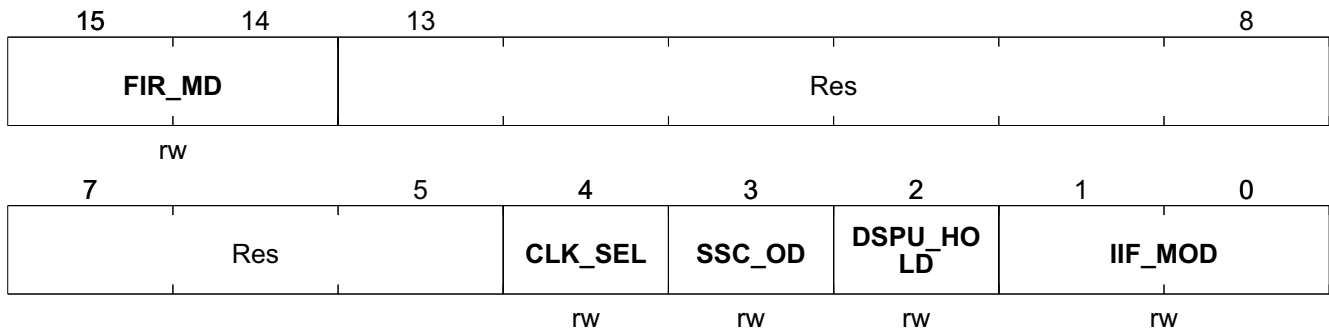
**AREV** **Offset** **Reset Value**  
**Angle Revolution Register** **04<sub>H</sub>** **8000<sub>H</sub>**





**Interface Mode1 Register**

**MOD\_1** **Offset** **Reset Value**  
**Interface Mode1 Register** **06<sub>H</sub>** **8001<sub>H</sub>**



Field	Bits	Type	Description
FIR_MD	15:14	rw	<b>Filter Decimation Setting</b> 00 <sub>B</sub> 21.3µs 01 <sub>B</sub> 42.7µs 10 <sub>B</sub> 85.3µs 11 <sub>B</sub> 170.6µs Reset: 10 <sub>B</sub>
CLK_SEL	4	rw	<b>Clock Source Select</b> 0 <sub>B</sub> internal oscillator 1 <sub>B</sub> external 4MHz clock Reset: 0 <sub>B</sub>
SSC_OD	3	rw	<b>SSC-Interface</b> 0 <sub>B</sub> Push-Pull 1 <sub>B</sub> Open Drain (default within TLE5012-E0318 and TLE5012-E0742) Reset: 0 <sub>B</sub>
DSPU_HOLD	2	rw	<b>Hold DSPU Operation</b> 0 <sub>B</sub> DSPU in normal schedule operation 1 <sub>B</sub> DSPU is on hold Reset: 0 <sub>B</sub>
IIF_MOD	1:0	rw	<b>Incremental Interface Mode</b> 00 <sub>B</sub> IIF disabled 01 <sub>B</sub> A/B operation with Index on DATA 10 <sub>B</sub> not allowed 11 <sub>B</sub> not allowed Reset: 01 <sub>B</sub>

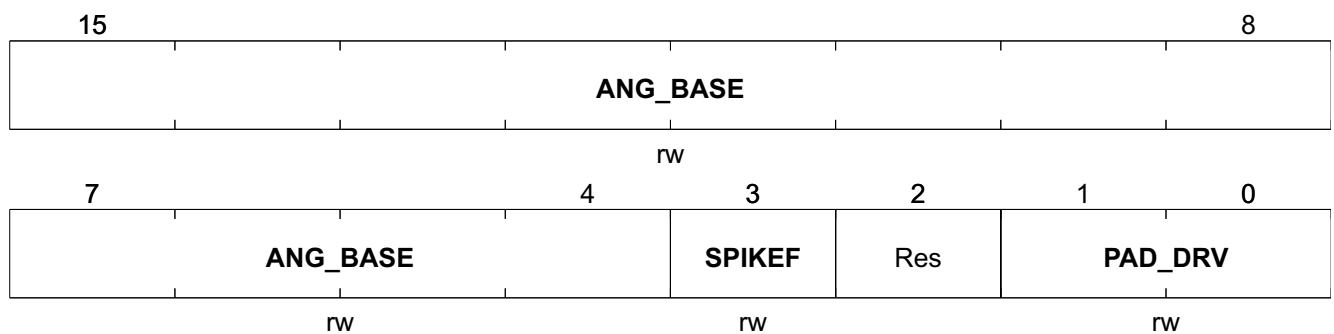




Field	Bits	Type	Description
AUTOCAL	1:0	rw	<b>Autocalibration Mode</b> 00 <sub>B</sub> no autocalibration 01 <sub>B</sub> autocalibration time mode (1LSB parameter change every $t_{upd}$ ) (default within TLE5012-E0318 and TLE5012-E0742) 10 <sub>B</sub> autocalibration angle mode1 (1LSB parameter change every 22.5°) 11 <sub>B</sub> autocalibration angle mode2 (1LSB parameter change every 11.25°) Reset: 00 <sub>B</sub>

**Interface Mode3 Register**

MOD_3	Offset	Reset Value
Interface Mode3 Register	09 <sub>H</sub>	0000 <sub>H</sub>



Field	Bits	Type	Description
ANG_BASE	15:4	rw	<b>Angle Base</b> 800 <sub>H</sub> -180° 000 <sub>H</sub> 0° 001 <sub>H</sub> 0.0879° 7FF <sub>H</sub> +179.912° Reset: 000 <sub>H</sub>
SPIKEF	3	rw	<b>Analog Spike Filters of Input Pads</b> 0 <sub>B</sub> spike filter disabled 1 <sub>B</sub> spike filter enabled Reset: 0 <sub>B</sub>







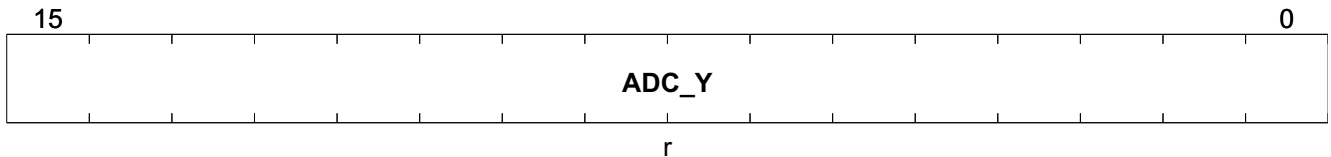






**Y-row Value Register**

<b>ADC_Y</b>	<b>Offset</b>	<b>Reset Value</b>
Y-row value	11 <sub>H</sub>	0000 <sub>H</sub>



Field	Bits	Type	Description
ADC_Y	15:0	r	<b>ADC value of Y-GMR</b> Updated when ADC_X or ADC_Y is read. Reset: 0 <sub>H</sub>

**3.5.2 Pulse Width Modulation Interface**

The **Pulse Width Modulation (PWM)** Interface can be selected by connecting CLK to V<sub>DD</sub>.

The PWM update rate can be programmed within the register 0E<sub>H</sub> (IFAB\_RES) in following steps:

- 0.25 kHz with 12 bit resolution
- 0.5 kHz with 11 bit resolution
- 1.0 kHz with 10 bit resolution (default)
- 2.0 kHz with 9 bit resolution

PWM uses a square wave with constant frequency whose duty cycle is modulated resulting in an average value of the waveform.

**Figure 21** shows the principle behavior of a PWM with different duty cycles and the definition of timing values. The duty cycle of a PWM is defined by following general formulas:

$$\begin{aligned}
 \text{Duty Cycle} &= \frac{t_{on}}{t_{PWM}} \\
 t_{PWM} &= t_{on} + t_{off} \\
 f_{PWM} &= \frac{1}{t_{PWM}}
 \end{aligned}
 \tag{3}$$

The range between 0 - 6.25% and 93.75 - 100% is used only for diagnostic purposes. More details are given in **Table 16**.

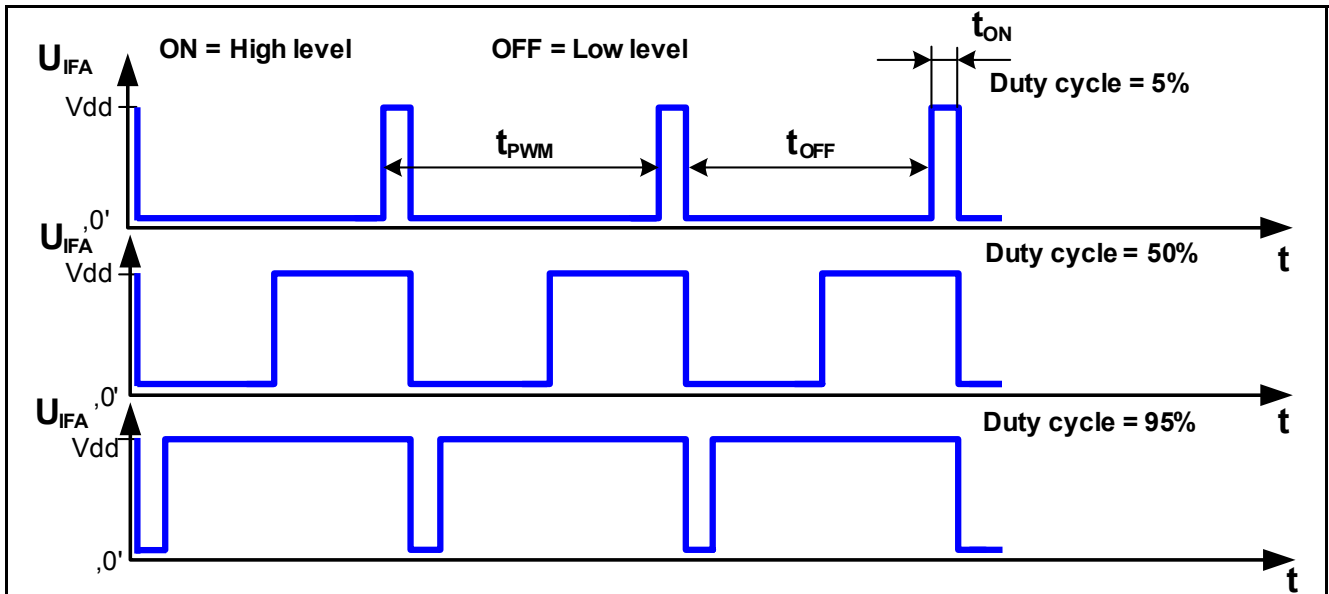


Figure 21 Typical Example for a PWM Signal

Table 16 PWM Interface

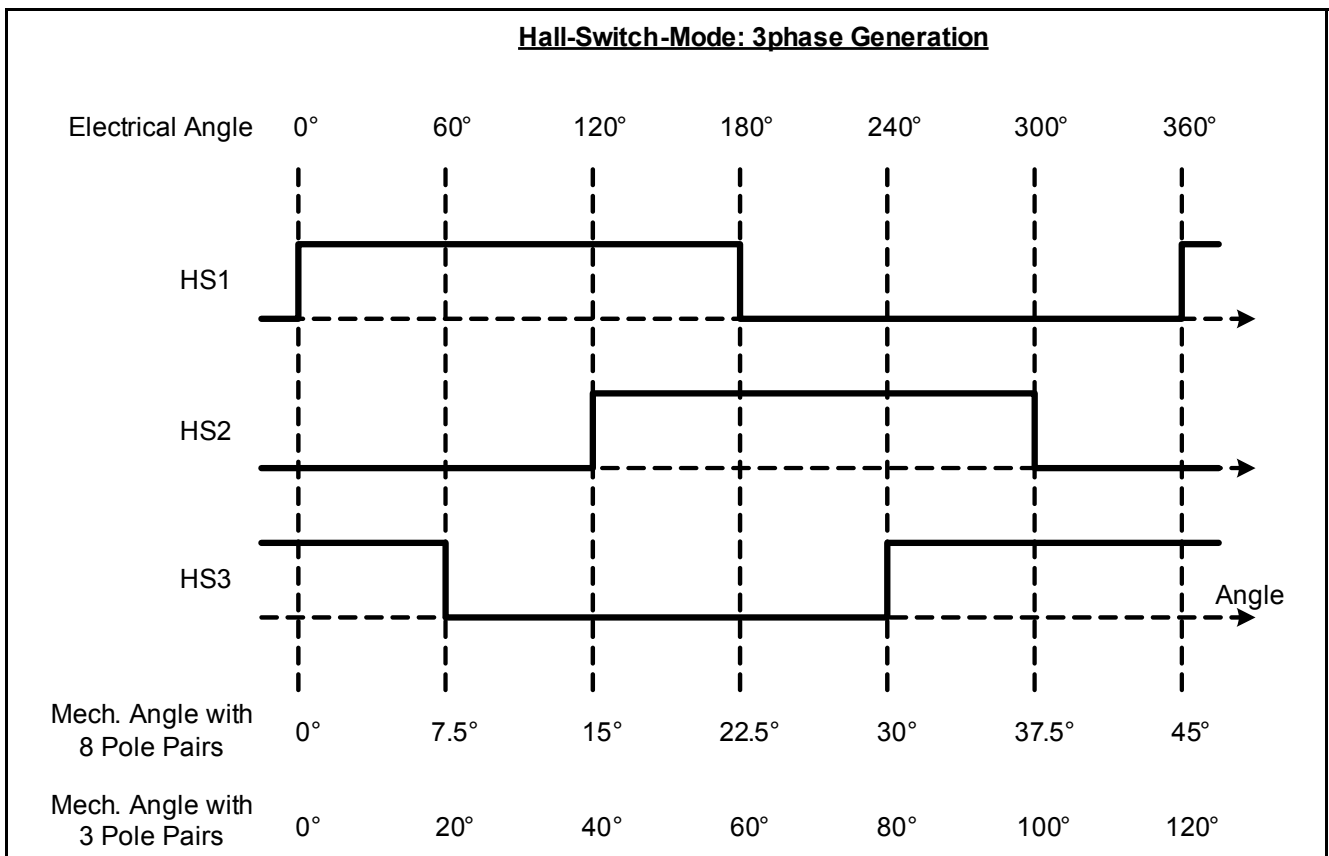
Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
PWM Output Frequency	$f_{PWM}$	244	-	1953	Hz	selectable by IFAB_RES <sup>1)</sup>
Output Duty Cycle Range	$DY_{PWM}$	6.25	-	93.75	%	Absolute Angle
		-	2	-	%	Electrical Error (S_RST; S_VR)
		-	98	-	%	System Error (S_FUSE; S_OV; S_XYOL; S_MAGOL; S_ADCT)
		0	-	1	%	Short to GND
		99	-	100	%	Short to V <sub>DD</sub> , Power-Loss
PWM Period Variation	$t_{PWMvar}$	-5	-	5	%	<sup>2)</sup>

1)  $f_{PWM} = (f_{DIG} * 2^{IFAB\_RES}) / (24 * 4096)$

2) depends on internal oscillator frequency variation ([Chapter 3.4.6](#))

### 3.5.3 Hall Switch Mode

The **Hall Switch Mode (HSM)** within the TLE5012 allows to emulate the output of three Hall switches. Hall switches are often used in electrical commutated motors to get information of the rotor position. With these three output signals the motor will be commutated in the right way. Depending on the used pole pairs of the rotor, different amount of electrical periods have to be realized. This is selectable within  $0E_H$  (HSM\_PLP). Within the TLE5012-E0318 three polepairs and within the TLE5012-E0742 seven polepairs are fused. **Figure 22** depicts the three output signals with the relationship between electrical angle and mechanical angle. The mechanical  $0^\circ$  point is always used as reference.



**Figure 22 Hall Switch Mode**

The HSM Interface can be selected by connecting CLK to GND and CSQ has to be logic "1".

**Table 17 Hall Switch Mode**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Rotation Speed	n	-	-	10000	rpm	



**Table 17 Hall Switch Mode**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Electrical Angle Accuracy	$\alpha_{\text{elect}}$	-	1.2	2	°	2 polepairs with autocalibration <sup>1)2)</sup>
		-	1.8	3		3 polepairs with autocal. <sup>1)2)</sup>
		-	2.4	4		4 polepairs with autocal. <sup>1)2)</sup>
		-	3.6	6		6 polepairs with autocal. <sup>1)2)</sup>
		-	4.2	7		7 polepairs with autocal. <sup>1)2)</sup>
		-	4.8	8		8 polepairs with autocal. <sup>1)2)</sup>
		-	7.2	12		12 polepairs with autocal. <sup>1)2)</sup>
-	9.6	16	16 polepairs with autocal. <sup>1)2)</sup>			
Mechanical Angle Switching Hysteresis	$\alpha_{\text{HShystm}}$	0	-	0.625	°	selectable by IFAB_HYST <sup>3)</sup>
Electrical Angle Switching Hysteresis <sup>4)</sup>	$\alpha_{\text{HShystel}}$	-	1.25	-	°	2 polepairs; IFAB_HYST=11 <sup>1)2)</sup>
		-	1.88	-		3 polepairs; IFAB_HYST=11 <sup>1)2)</sup>
		-	2.50	-		4 polepairs; IFAB_HYST=11 <sup>1)2)</sup>
		-	3.75	-		6 polepairs; IFAB_HYST=11 <sup>1)2)</sup>
		-	4.38	-		7 polepairs; IFAB_HYST=11 <sup>1)2)</sup>
		-	5.00	-		8 polepairs; IFAB_HYST=11 <sup>1)2)</sup>
		-	7.50	-		12 polepairs; IFAB_HYST=11 <sup>1)2)</sup>
-	10	-	16 polepairs; IFAB_HYST=11 <sup>1)2)</sup>			
Fall Time	$t_{\text{HSfall}}$	-	0.02	1	µs	$R_L = 2.2\text{k}\Omega; C_L < 50\text{pF}$
Rise Time	$t_{\text{HSrise}}$	-	0.4	1	µs	$R_L = 2.2\text{k}\Omega; C_L < 50\text{pF}$

- 1) depends on internal oscillator frequency variation ([Chapter 3.4.6](#))
- 2) guaranteed by design
- 3) including GMR hysteresis
- 4) The hysteresis has to be considered only at change of rotation direction.

To avoid switching on mechanical vibrations of the rotor, a hysteresis is recommended ([Figure 23](#)).

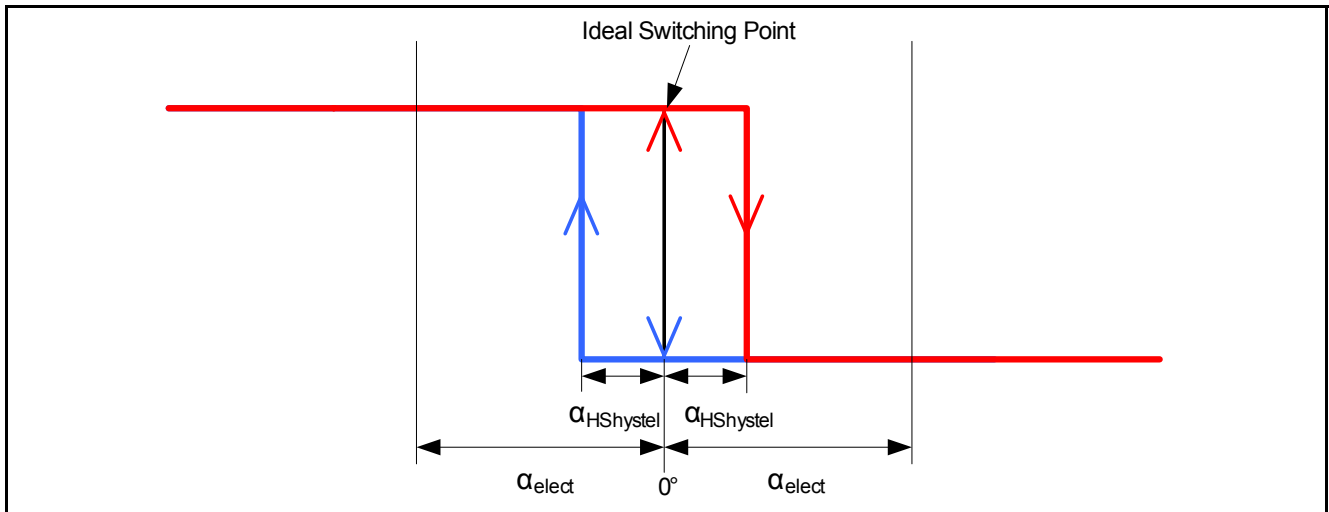


Figure 23 HS Hysteresis

### 3.5.4 Incremental Interface

The Incremental Interface (IIF) uses an up/down counter of a microcontroller for the angle transmission. The synchronization is done by the parallel active SSC-Interface. The angle value read out by the SSC-Interface can be compared with the stored counter value. In case of a non-synchronization, the microcontroller add the difference to the actual counter value to synchronize the TLE5012 with the microcontroller. The resolution of the IIF can be selected within the interface mode4 register (MOD\_4) under IFAB\_RES.

#### A/B Mode

The phase shift between phase A and B indicates a clockwise (B follows A) or a counterclockwise (A follows B) rotation of the magnet.

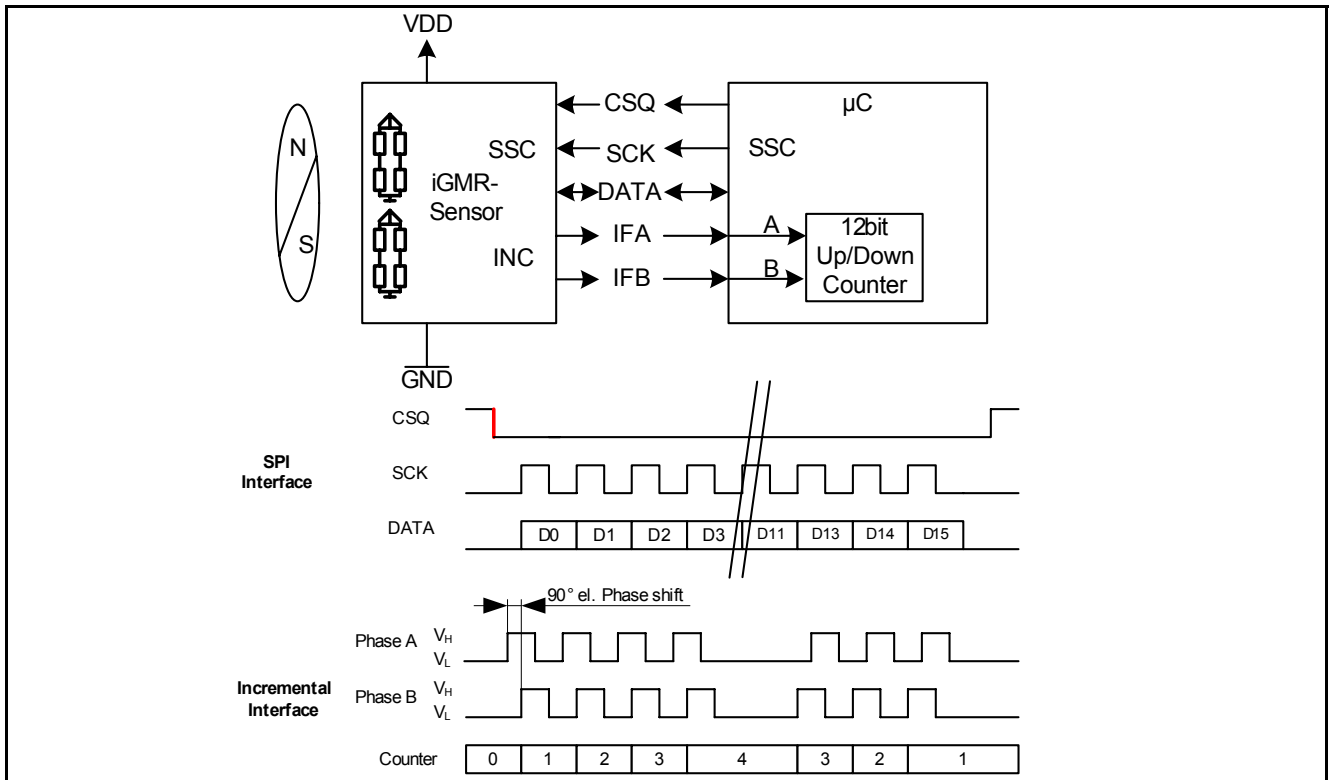


Figure 24 Incremental Interface Protocol with symbolically illustration of SPI-Interface

### Index Signal

The Index-Signal is generated via Data pin, while CSQ is high (no SSC-communication). The Index-Signal is coded in quadrants via a PWM-sequence, [Figure 25](#).

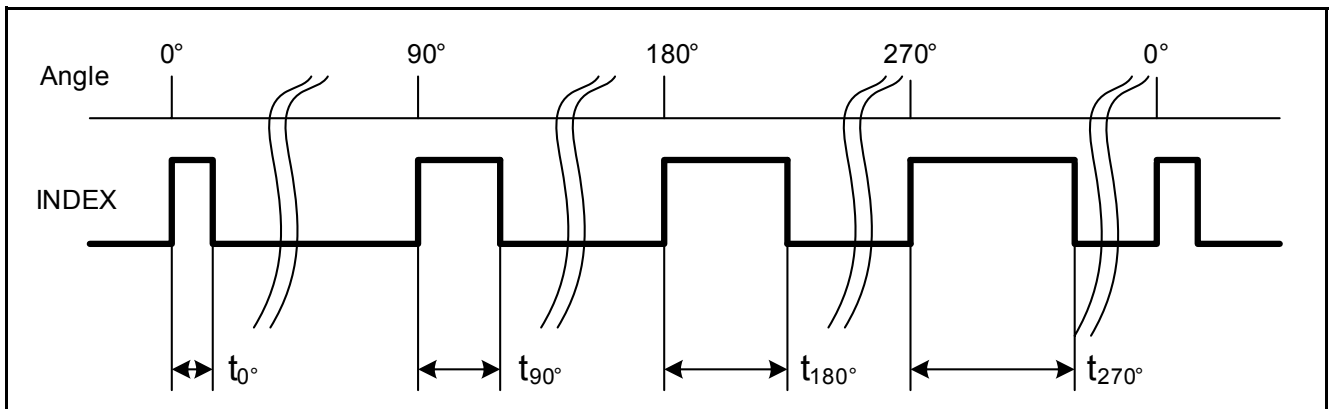


Figure 25 IIF Index Coding

Table 18 Incremental Interface

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Incremental output Frequency	$f_{inc}$	-	-	1.0	MHz	Frequency of Phase A and Phase B

**Table 18 Incremental Interface (cont'd)**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Index	$t_{0^\circ}$	-	5	-	$\mu\text{s}$	$0^\circ$
	$t_{90^\circ}$	-	10	-	$\mu\text{s}$	$90^\circ$
	$t_{180^\circ}$	-	15	-	$\mu\text{s}$	$180^\circ$
	$t_{270^\circ}$	-	20	-	$\mu\text{s}$	$270^\circ$

### 3.6 Test Structure

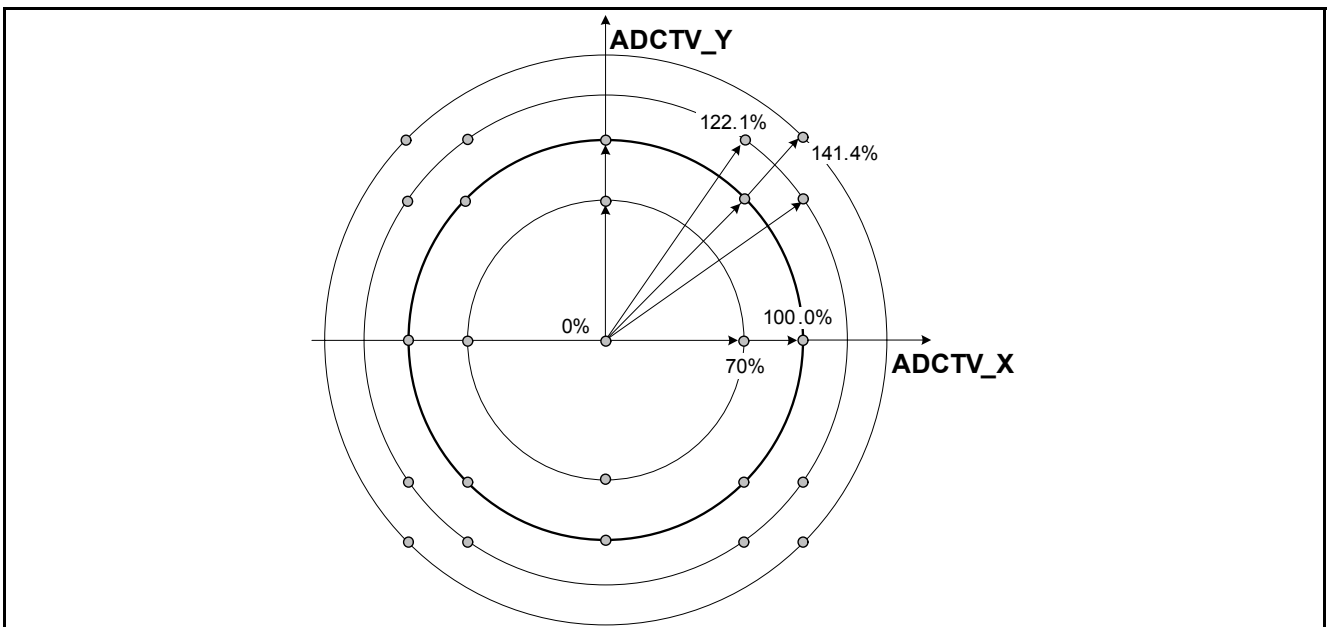
#### 3.6.1 ADC Test Vectors

It is possible to feed the ADCs with appropriate values to simulate a certain magnet position and other GMR effects. This test can be activated within SIL register (ADCTV\_EN). With ADCTV\_Y and ADCTV\_X the vector length can be adjusted like [Figure 26](#).

The values are generated with resistors on the chip.

The following X/Y ADC values can be programmed:

- 4 points, circle amplitude = 70% ( $0^\circ, 90^\circ, 180^\circ, 270^\circ$ )
- 8 points, circle amplitude = 100% ( $0^\circ, 45^\circ, 90^\circ, 135^\circ, 180^\circ, 225^\circ, 270^\circ, 315^\circ$ )
- 8 points, circle amplitude = 122.1% ( $35.3^\circ, 54.7^\circ, 125.3^\circ, 144.7^\circ, 215.3^\circ, 234.7^\circ, 305.3^\circ, 324.7^\circ$ )
- 4 points, circle amplitude = 141.4% ( $45^\circ, 135^\circ, 225^\circ, 315^\circ$ )



**Figure 26 ADC Test Vectors**

### 3.7 Overvoltage Comparators

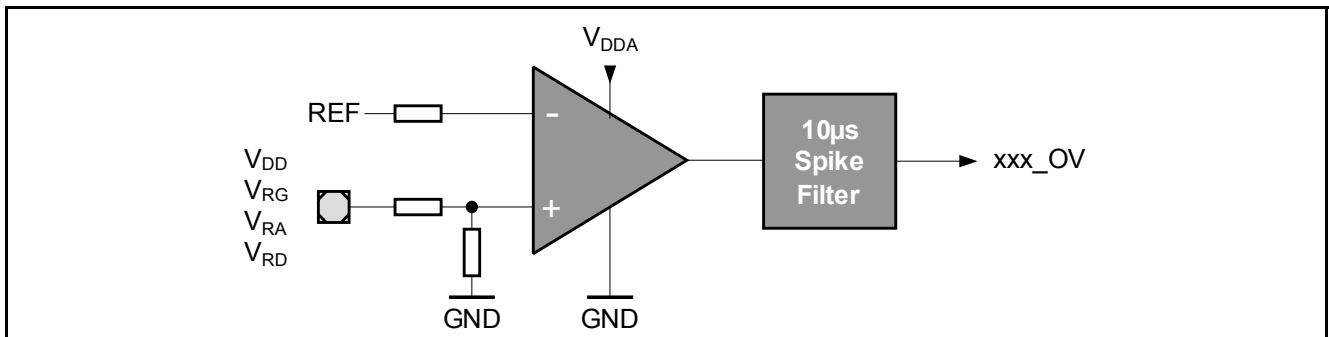
Various comparators monitor the voltage in order to ensure error free operation. The overvoltages must be active at least 256 periods of  $t_{DIG}$  to set the test comparator bits in the SSC Interface registers. This works as digital spike suppression.

**Table 19 Test Comparators**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Overvoltage Detection	$V_{OVG}$	-	2.80	-	V	
	$V_{OVA}$	-	2.80	-	V	
	$V_{OVD}$	-	2.80	-	V	
$V_{DD}$ Overvoltage	$V_{DDOV}$	-	6.05	-	V	
$V_{DD}$ Undervoltage	$V_{DDUV}$	-	2.70	-	V	
GND - Off Voltage	$V_{GNDoff}$	-	-0.55	-	V	
$V_{DD}$ - Off Voltage	$V_{VDDoff}$	-	0.55	-	V	
Spike Filter Delay	$t_{DEL}$	-	10	-	$\mu$ s	

#### 3.7.1 Internal Supply Voltage Comparators

Every voltage regulator has an overvoltage comparator to detect a malfunction. If the nominal output voltage of 2.5 V is larger than  $V_{OVG}$ ,  $V_{OVA}$  and  $V_{OVD}$ , then this overvoltage comparator is activated.



**Figure 27 OV Comparator**

#### 3.7.2 $V_{DD}$ Overvoltage Detection

The Overvoltage Detection Comparator monitors the external supply voltage at the  $V_{DD}$  pin. It activates the  $S_{VR}$  bit. (Figure 27)

#### 3.7.3 GND - Off Comparator

The GND - Off Comparator is used to detect a voltage difference between the GND pin and SCK. It activates the  $S_{VR}$  bit of the SSC - Interface. This circuit can detect a disconnection of the Supply GND Pin.

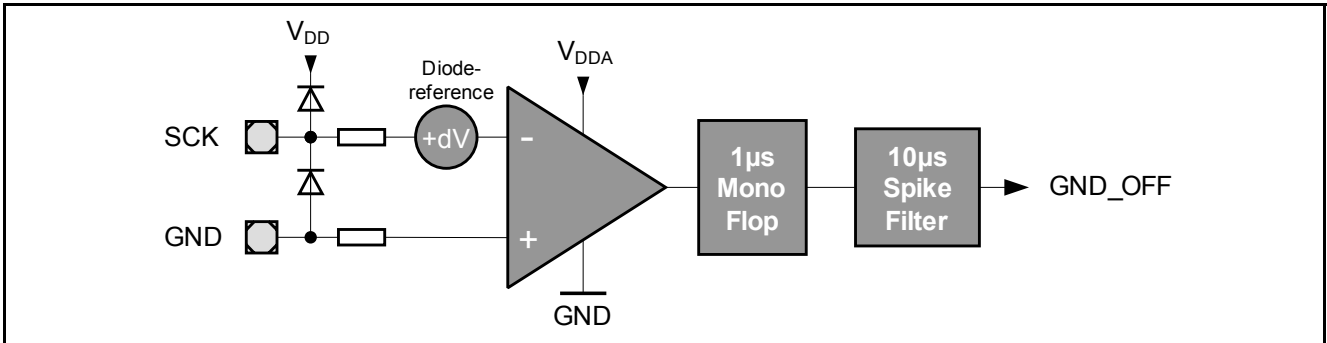


Figure 28 GND - Off Comparator

### 3.7.4 V<sub>DD</sub> - Off Comparator

The V<sub>DD</sub> - Off Comparator detects a disconnection of the VDD pin supply voltage. In this case, the TLE5012 is supplied by the SCK and CSQ input pins via the ESD structures. It activates the S\_VR bit.

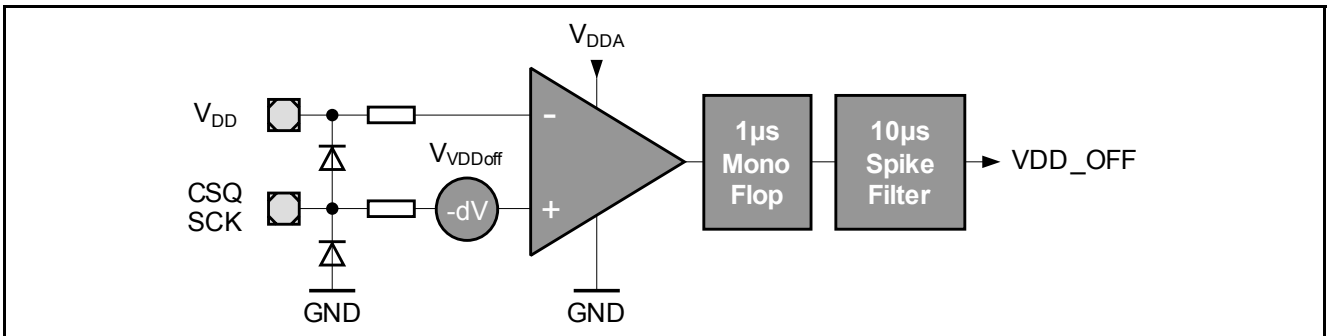


Figure 29 V<sub>DD</sub> - Off Comparator

## 4 Package Information

### 4.1 Package Parameters

Table 20 Package Parameters

Parameter	Symbol	Limit Values			Unit	Notes
		min.	typ.	max.		
Thermal Resistance	$R_{thJA}$	-	150	200	K/W	Junction to Air <sup>1)</sup>
	$R_{thJC}$	-	-	75	K/W	Junction to Case
	$R_{thJL}$	-	-	85	K/W	Junction to Lead
Soldering Moisture Level		MSL 3				260°C
Lead Frame		Cu				
Plating		Sn 100%				> 7 $\mu$ m

1) according to Jedec JESD51-7

### 4.2 Package Outline

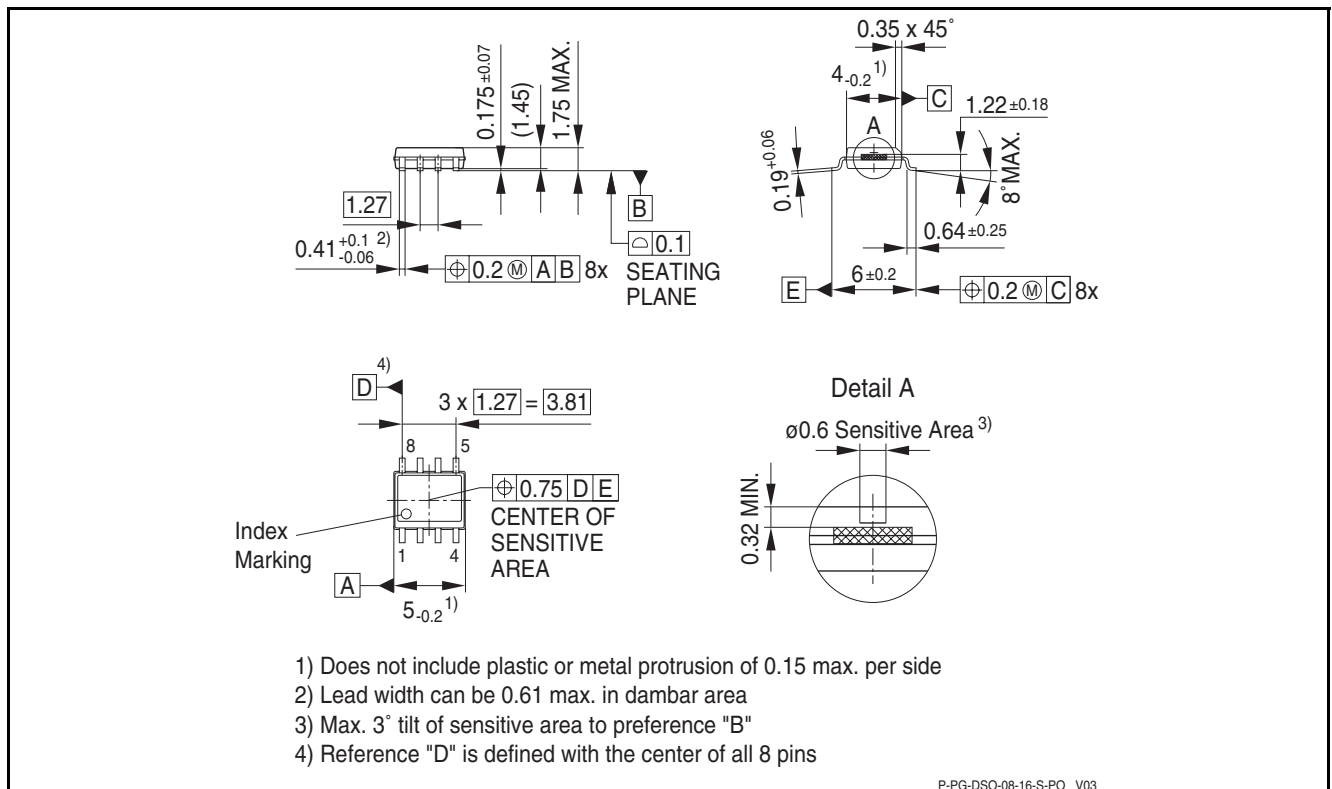


Figure 30 PG-DSO-8 Package Dimension

### 4.3 Footprint

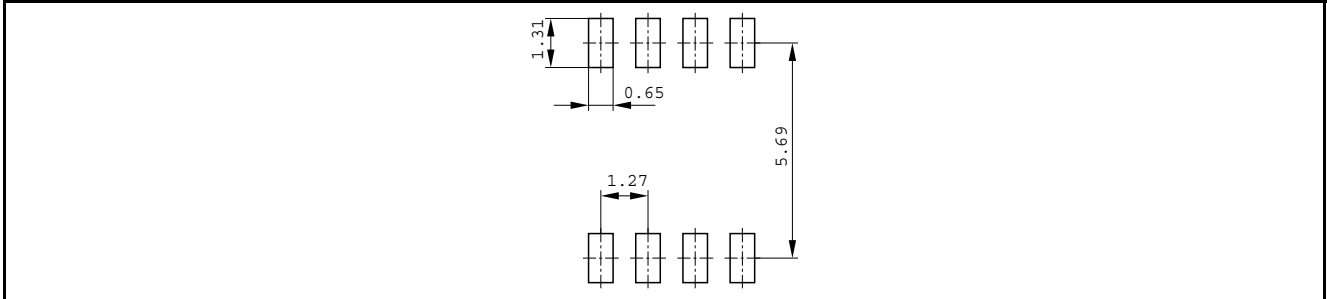


Figure 31 Footprint PG-DSO-8

### 4.4 Packing

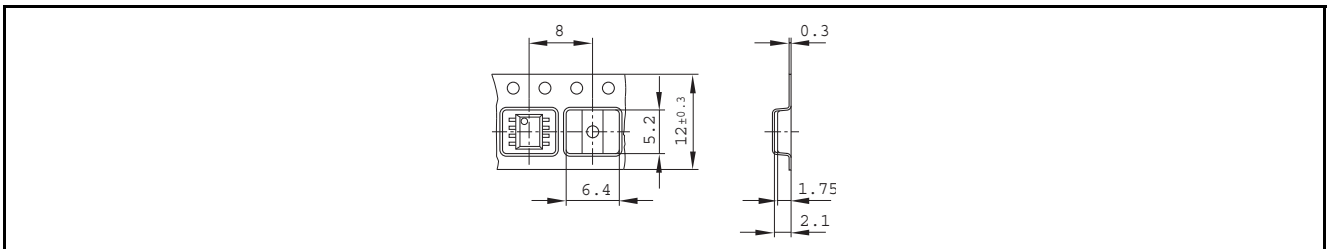


Figure 32 Tape and Reel

### 4.5 Marking

Position	Marking	Description
1st Line	5012xx	See ordering table on page 7
2nd Line	xxx	Lot code
3rd Line	Gxxxx	G..green, 4-digit..date code

### Processing

Note: For processing recommendations, please refer to Infineon's Notes on processing



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